



# **SOFC IC Overview and CTP Status**

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**Presented at SECA CTP IC Meeting,  
Argonne National Laboratory**

**July 28-29, 2004**

# outline

➤ IC Requirements

➤ IC/ SOFC Exposure Conditions

➤ IC Materials - Ceramic, Alloys, Coatings

➤ Technology Status

# SECA CTP Priorities

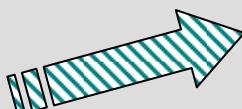
	<i>What</i>	<i>How</i>
1	Gas seals	Glass and compressive seals
1	Interconnect	Modifying components in alloys Coatings
2	Modeling	Models with electrochemistry Structural characterization
2	Cathode performance	Micro structure optimization Mixed conduction Interface modification
2	Anode/fuel processing	Metal oxides with interface modification Catalyst surface modification Characterize thermodynamics/kinetics
3	Power electronics	Direct DC to AC conversion DC to DC design for fuel cells
4	Material cost	Lower cost precursor processing Cost model methodology

# Workshop Findings

*(Workshop held in Atlanta, 2001)*

## Topical Area

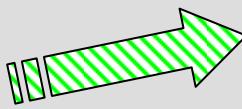
Cell/Stack Materials &  
Manufacturing



## Top 3 Development Needs

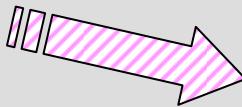
1. Stable Interconnect
2. Fuel/ Oxidant Seals
3. Internal Reforming/ Direct oxidation

Fuel processing



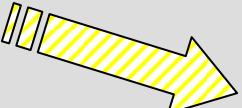
1. Sulfur Tolerant Anode
2. Catalyst Kinetics, Parameters & Deactivation
3. On anode Fuel Utilization

Stack/ Systems  
Performance & Modeling



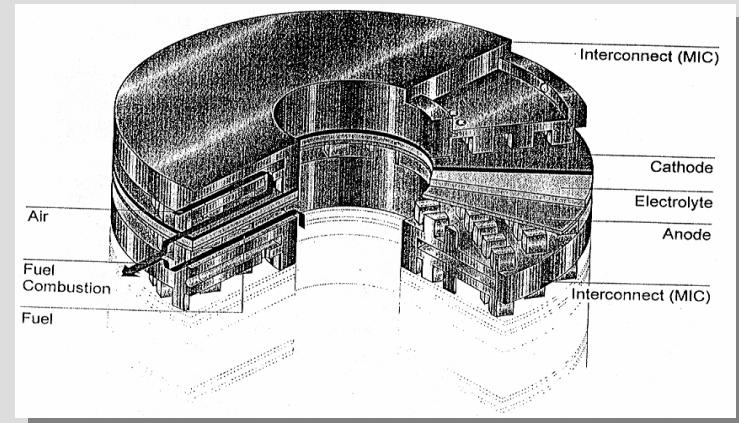
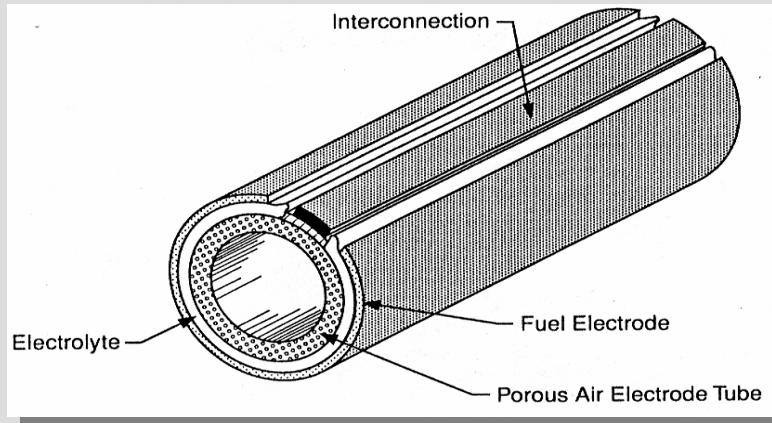
1. Fast start up and Thermal Cycles
2. Cell & Stack Performance Model
3. Low Cost HX, Insulation, Blowers & sensors

Power electronics

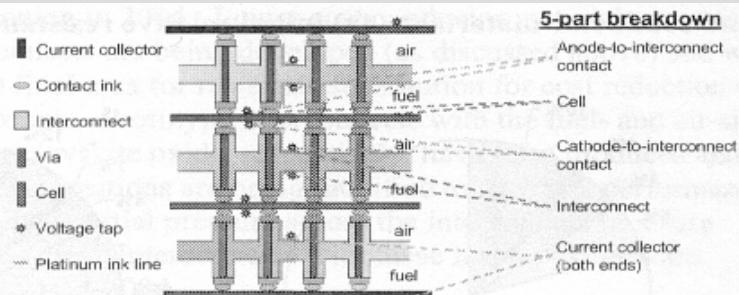
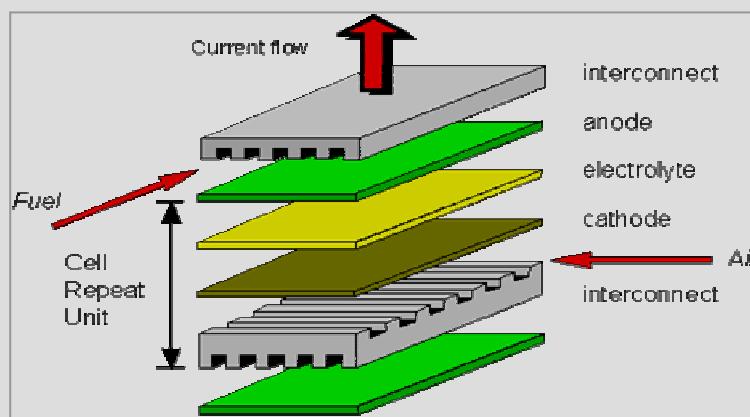


1. Fuel cell / PE Interface
2. Materials & Fabrication Processes
3. Modeling: Electrical Interfaces

# SOFC Configurations

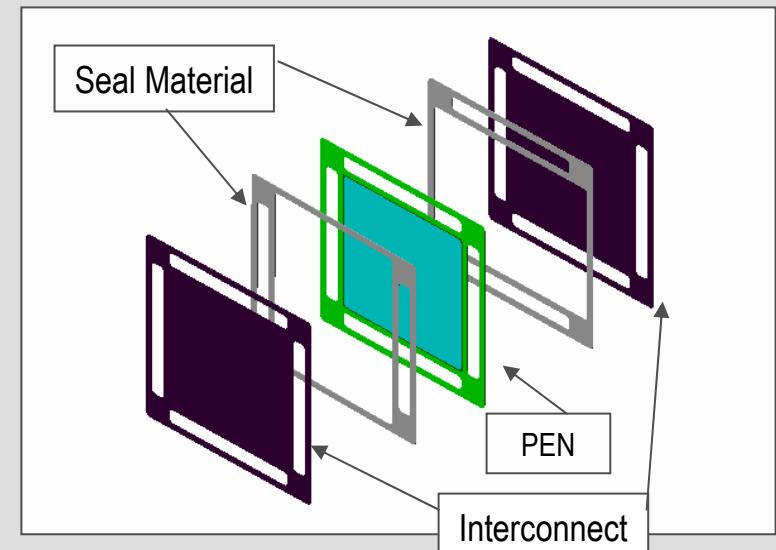
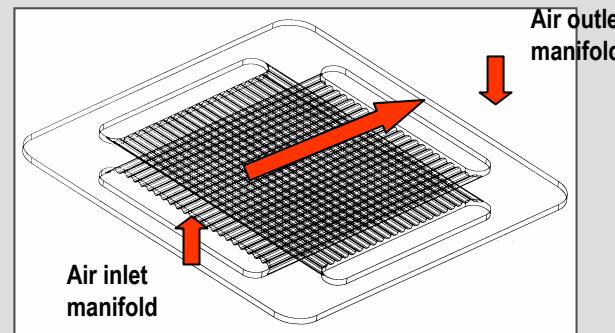
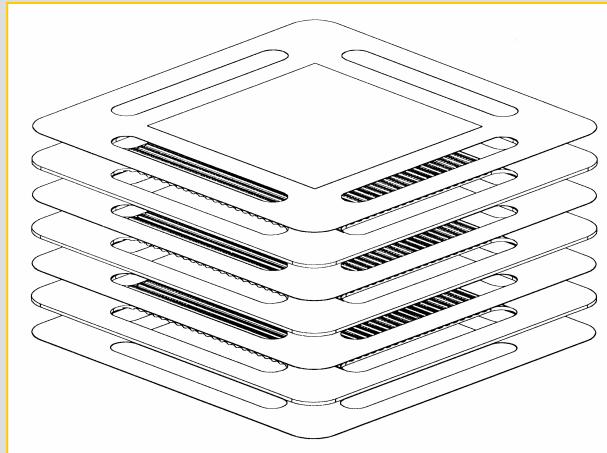


**Both ceramic and metallic interconnects have been used in SOFC systems**



**Figure 3. Illustration of short stack using voltage taps to isolate resistance contributions.**

# Planar SOFC Configurations



## Design Variables

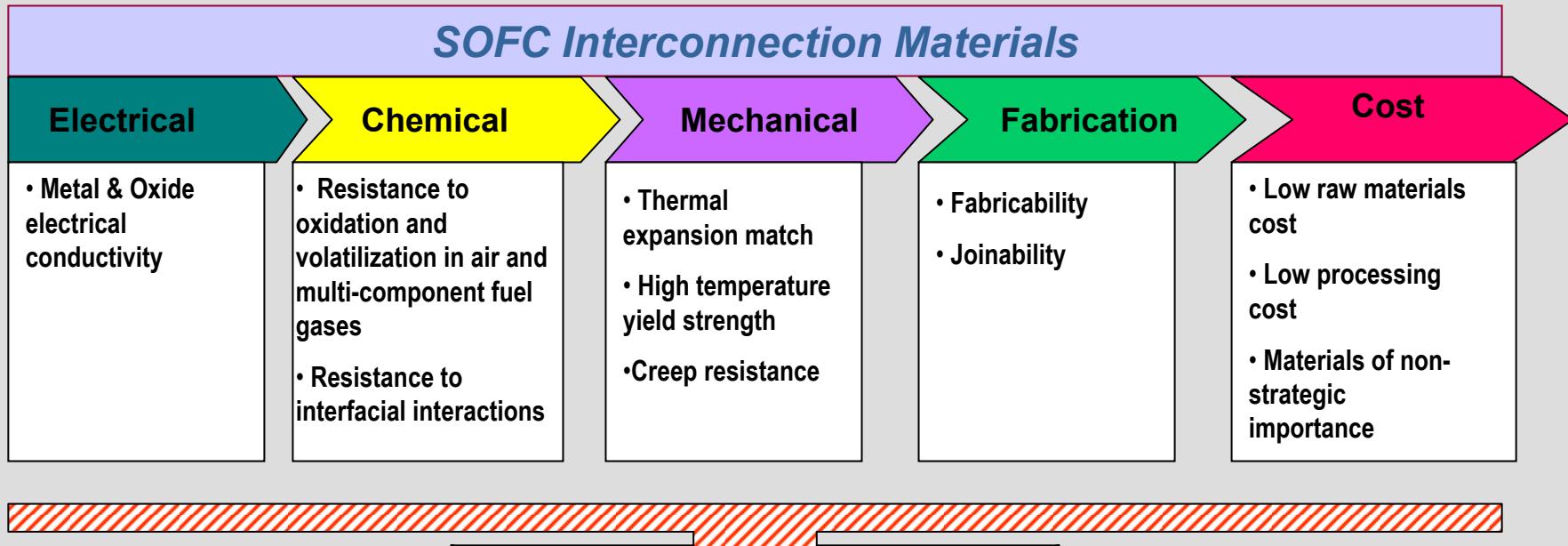
- Gas flow distribution channel dimensions/types
- Ceramic or metallic interconnect
- Material thickness and PEN strength
- Rigid or compression seals
- Manifold dimensions and Flow configuration

## Operational Variables

- 600-800C or higher
- Air as oxidant
- Hydrocarbon or reformed fuel
- 60-85% fuel utilization

# Interconnection Functional Requirements

*An integrated approach for IC development has been designed and implemented*



A Collaborative Program with Universities, National Laboratories, Manufacturers and Users

# SECA CTP IC Development

## Evaluation of metals and alloys:

- Fe base FSS, ASS
- Ni base alloys
- Silver and others

## Evaluation of Coatings:

- Ceramic w/wo Cr
- Claddings

## Evaluation of degradation mechanisms

- Corrosion in single & dual atmospheres
  - Interaction with Seals
  - Interaction with electrodes / interface layers

- Growth kinetics
- Electrical conductivity
- Chemical stability
- Interface stability
- Electrode compatibility

# SECA CTP Interconnect Activities

## PNNL

Evaluation of candidate alloys, surface modification of alloys, development of interconnect/cathode interfaces, evaluation/mitigation of Cr poisoning

## ANL

Evaluation/mitigation of Cr poisoning, development of alloy interconnects

## LBNL

Metal supported cells, protective coatings for alloys

## Univ. of Pittsburgh

Evaluation of chromia-forming alloys, accelerated testing, mechanisms

## Ceramatec

Protective coatings for interconnect alloys

# New Starts

## **Arcomac Surface Engineering, LLC**

Oxidation Resistant, Cr Retaining, Electrically Conductive Coatings on Metallic Alloys for SOFC interconnects

## **Southwest Research Institute**

Surface Modified Ferritic Interconnects for SOFCs

## **Southern Illinois University at Carbondale**

Novel alloy system, based on TiC-Ni-Ni<sub>3</sub>Al to develop a superior interconnect material for SOFC.

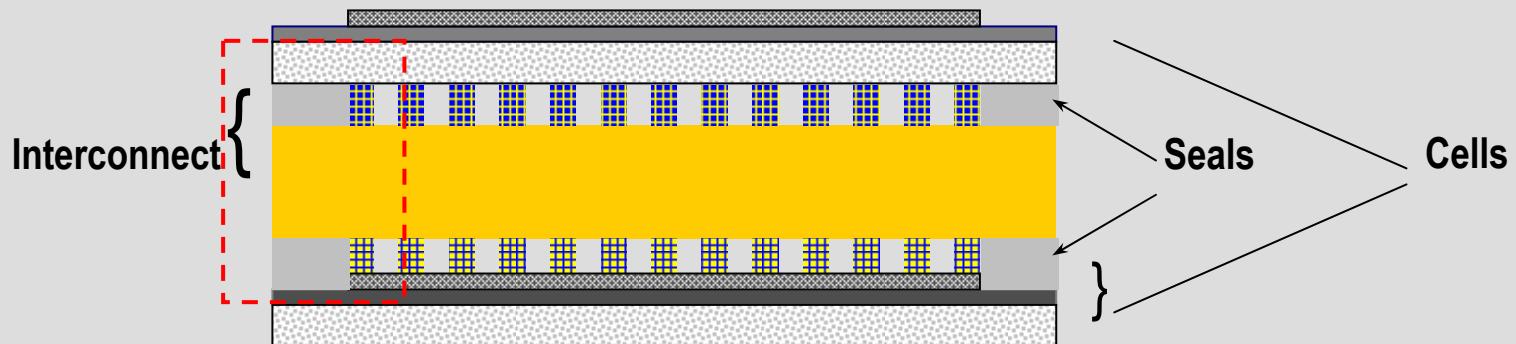
## **Tennessee Technological University**

Utilize alloy design principles to thermally-grow multi-layer structure with an outer layer of Cr-free nickel ferrite spinel and an inner layer of Ni-rich or Cr-rich protective oxide's

## **University of Utah**

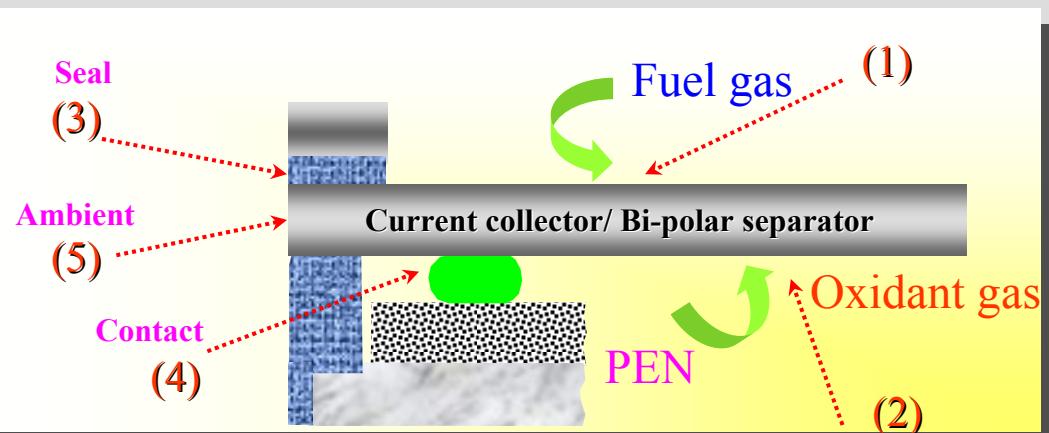
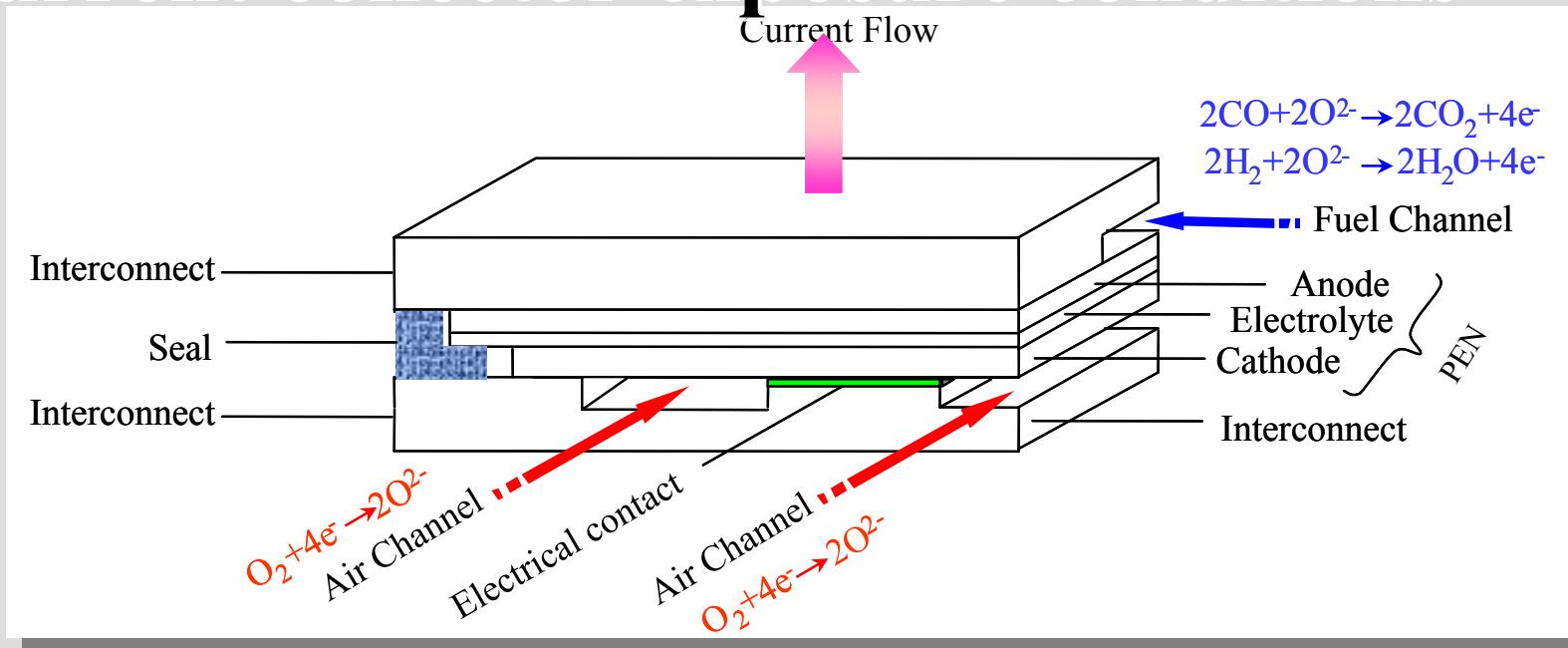
Synthesize and characterize coating materials with ultra-low oxygen diffusion that are electronically conducive using site-specific doping and through fundamental understanding of the underlying defect chemistry

# The Interconnect : Function



- ✓ Acts as a physical barrier between the fuel and oxidant (hermetic, chemically and mechanically stable, and thermally shock resistant)
- ✓ Acts as a low resistivity electrical conduit over the lifetime of the device
- ✓ Provides mechanical support and stability to the stack

# Current collector exposure conditions



1. Fuel gas/Metal interface
2. Oxidant gas/Metal interface
3. Compliant seal/Metal interface
4. Electrical contact/metal interface
5. Ambient/Metal interface

# Candidate IC Materials

## Three groups:

1. Electronically conducting Ceramic  
La Chromite (Doped)

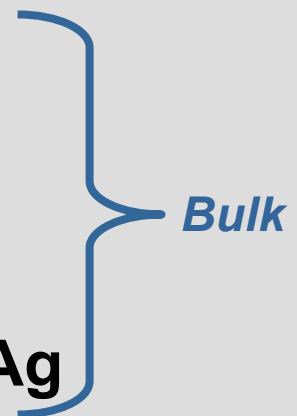
2. Metals and Alloys

Fe Base FSS & ASS, Ni base Alloys, Ag

3. Coatings & Claddings

Perovskites, Spinals, Ni (Anode)

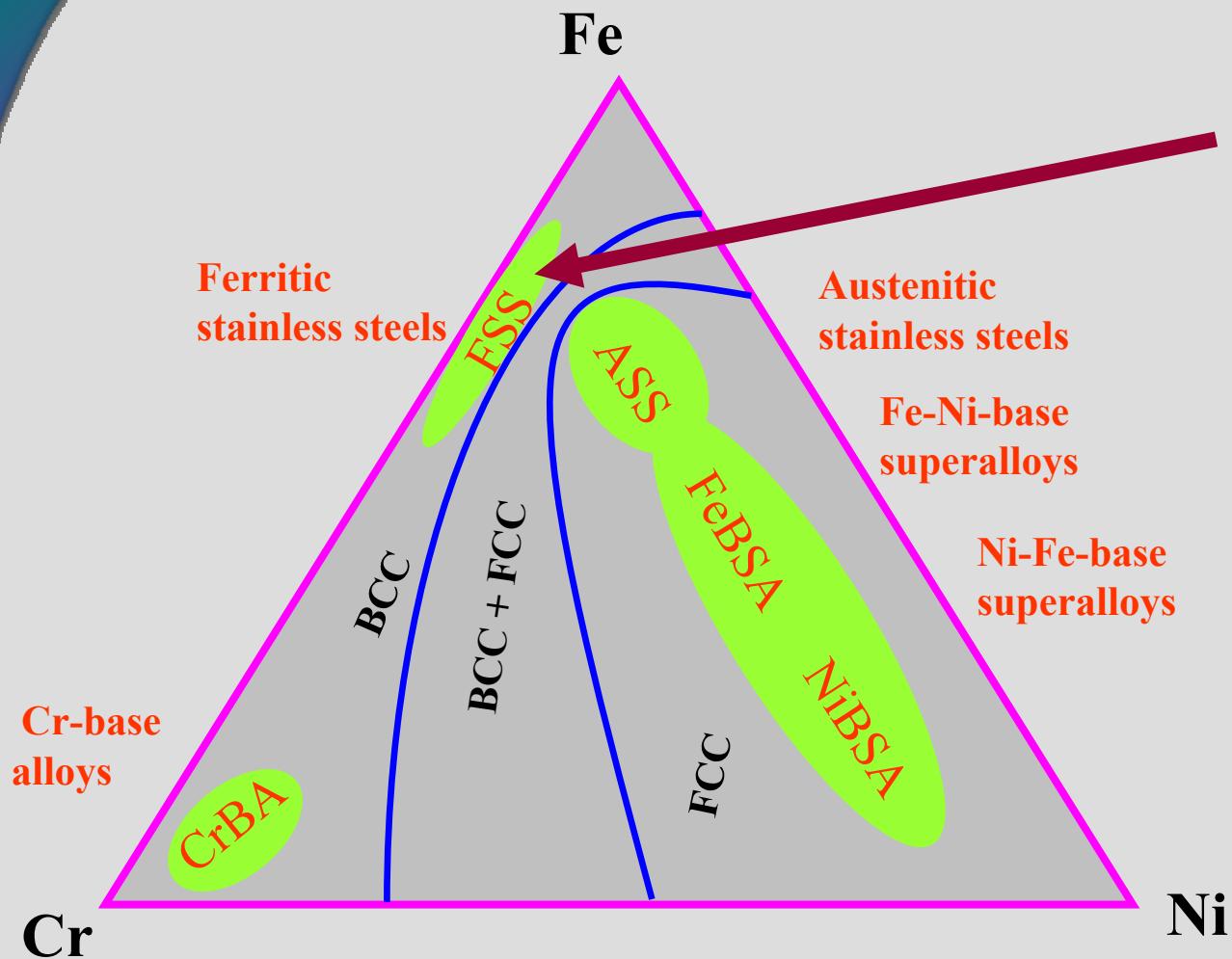
Bi & tri layer clad



# key properties of different alloy groups

Alloys	Matrix structure	TEC $\times 10^{-6} \cdot K^{-1}$	Oxidation resistance	Mechanical strengths	Manufacturability	Cost
CrBA	BCC	11.0-12.5 (RT-800°C)	Good	High	Difficult	Very expensive
FSS	BCC	11.5-14.0 (RT-800°C)	Good	Low	Fairly readily	Cheap
ASS	FCC	18.0-20.0 (RT-800°C)	Good	Fairly high	Readily	Cheap
FeBSA	FCC	15.0-20.0 (RT-800°C)	Good	High	Readily	Fairly expensive
NiBSA	FCC	14.0-19.0 (RT-800°C)	Good	High	Readily	Expensive

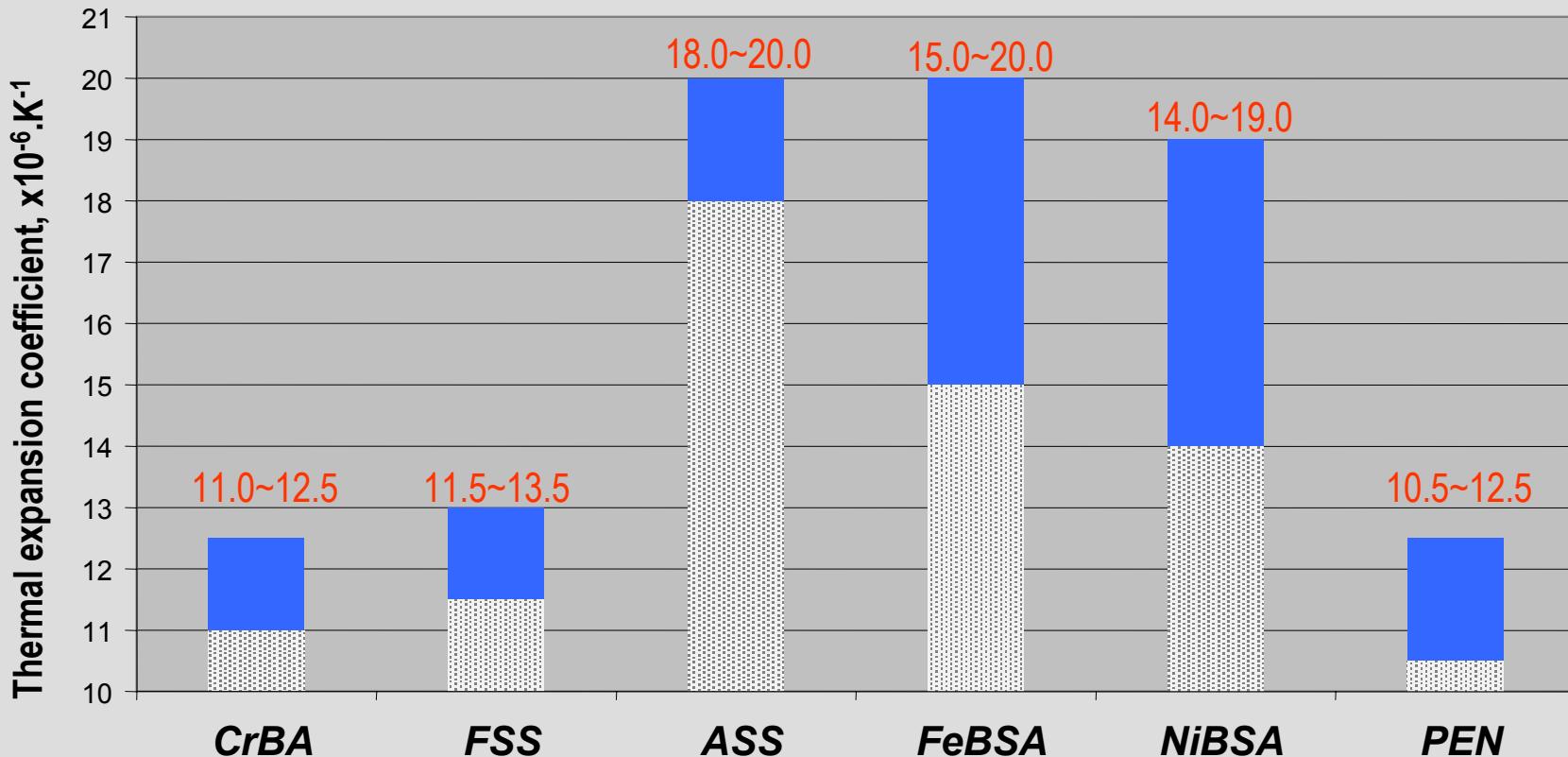
# Potential Candidate Alloy Systems



**Emphasis on  
“Chromia-forming”  
Ferritic Stainless  
Steels:**

- CTE match
- Conductive, protective oxide scale
- low cost
- ease of fabrication

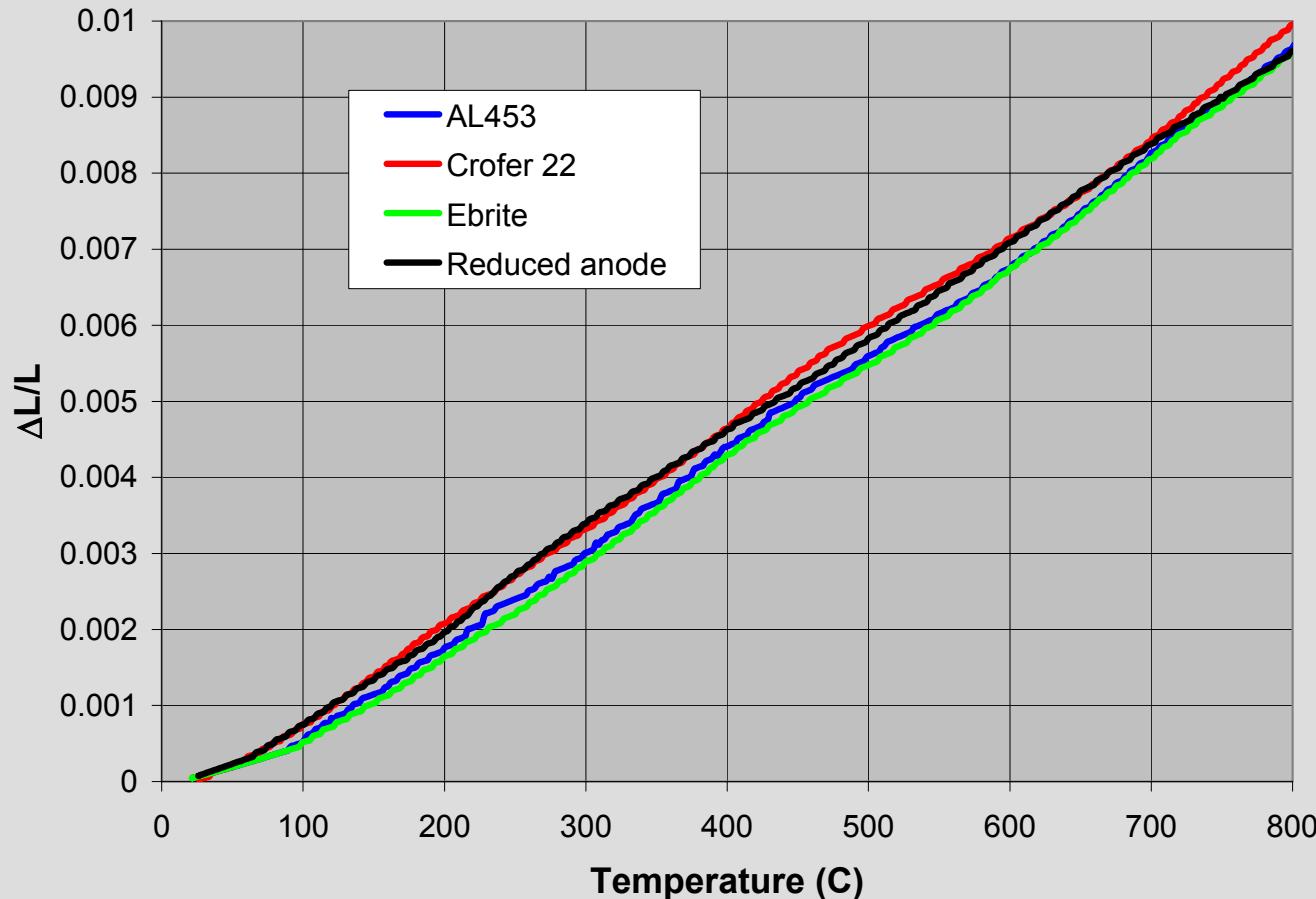
# CTE of different alloy groups



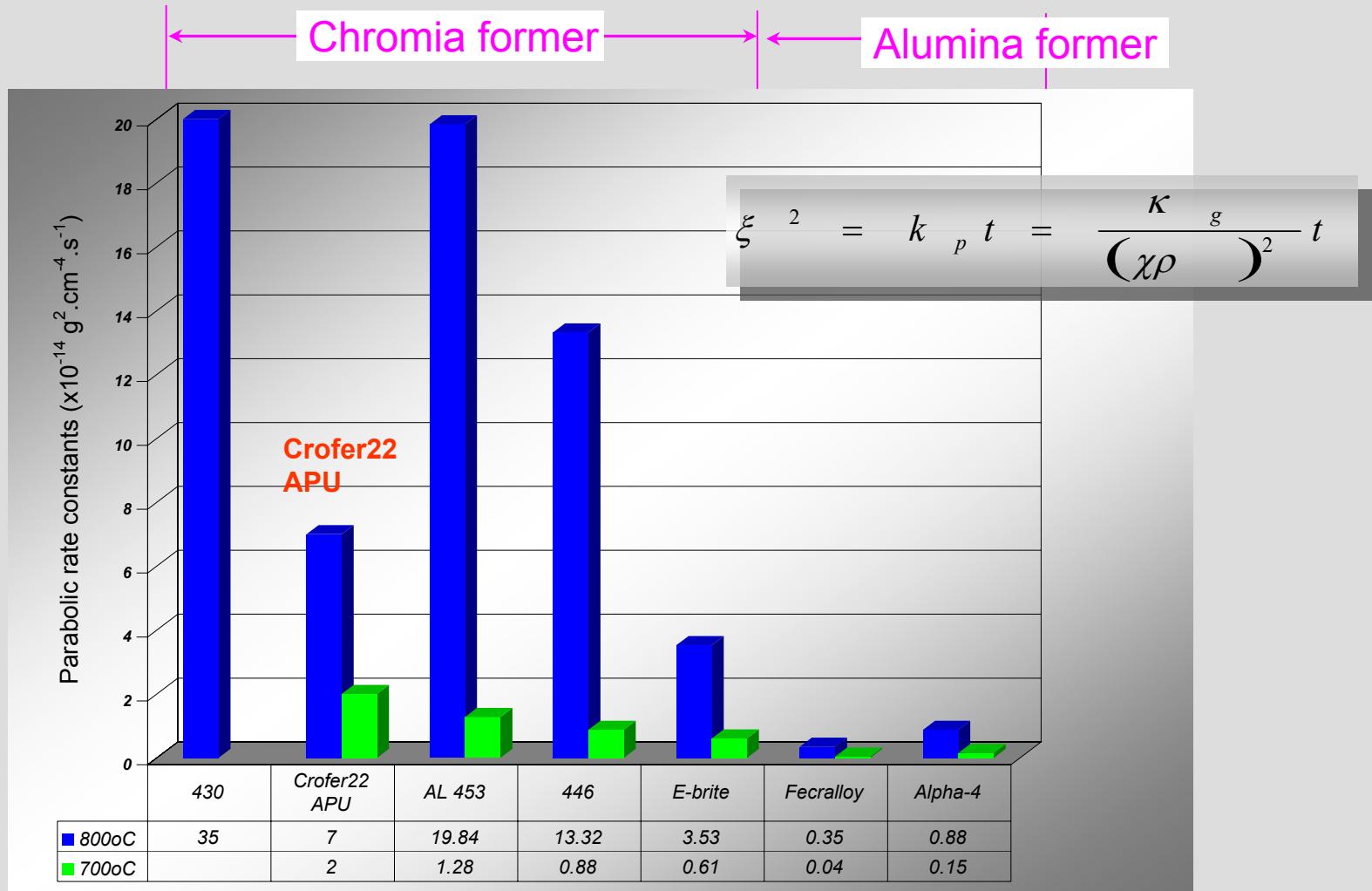
- BCC matrix alloys (CrBA, FSS) have a lower CTE than that of FCC matrix alloys (ASS, FeBSA, NiBSA);
- FSS, including Fecralloy offer better CTE match to PEN.

# Thermal expansion

Selected alloys offer good CTE match to SOFC components



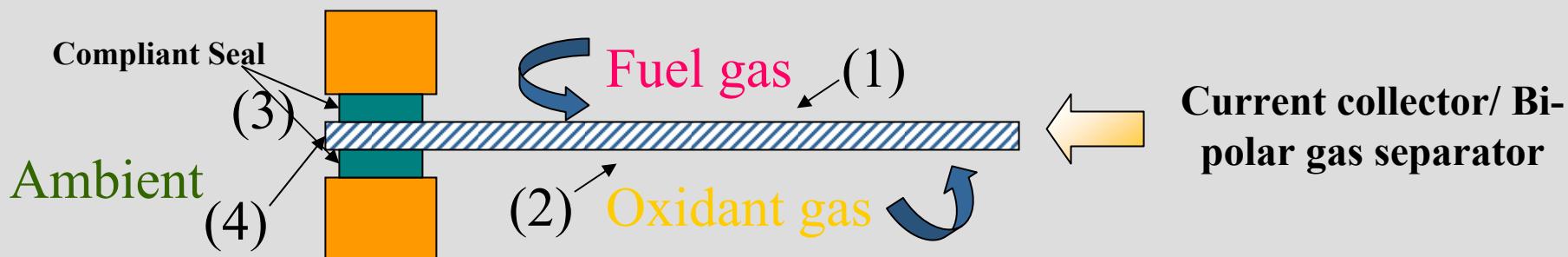
# Oxidation Resistance





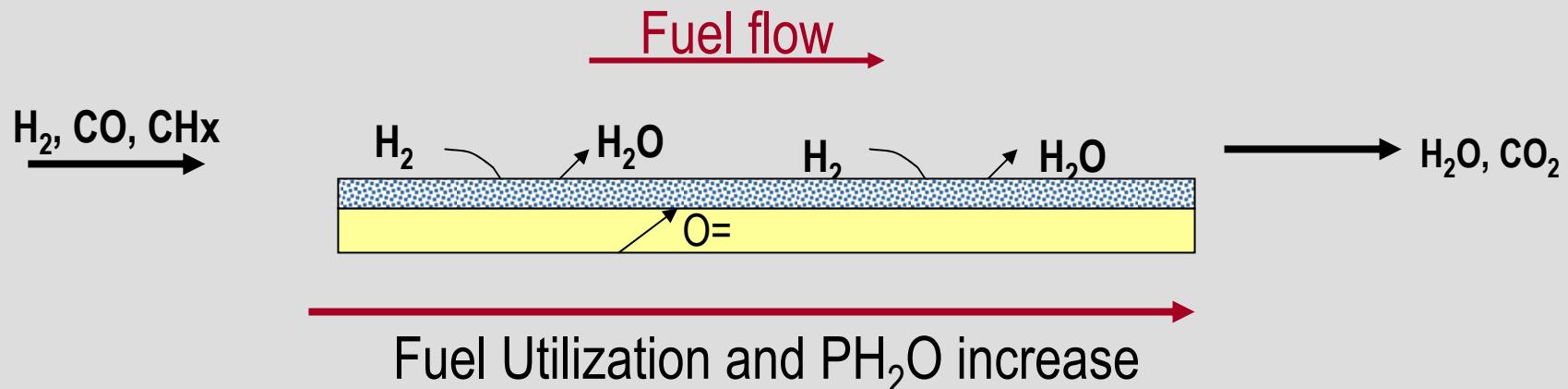
# SOFC Exposure : Corrosion & Oxidation

# Current collector exposure conditions



1. Fuel gas / Metal interface
2. Oxidant gas/ Metal interface
3. Compliant seal/ Metal interface
4. Ambient/ Metal interface

# Fuel Utilization: H<sub>2</sub>O Formation



$CH_x + H_2O = H_2 + CO$  (Consumption of H<sub>2</sub>O)  
 $H_2 + O^= = H_2O$  (Production of H<sub>2</sub>O)  
 $CO + H_2O = CO_2 + H_2$  (Consumption of H<sub>2</sub>O)

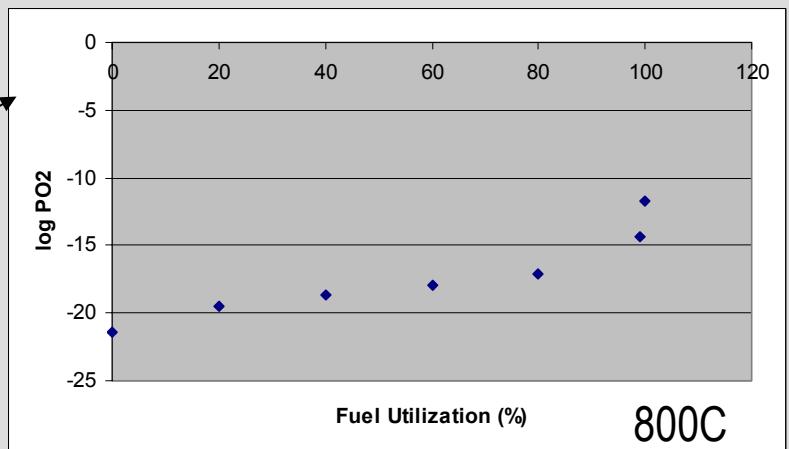
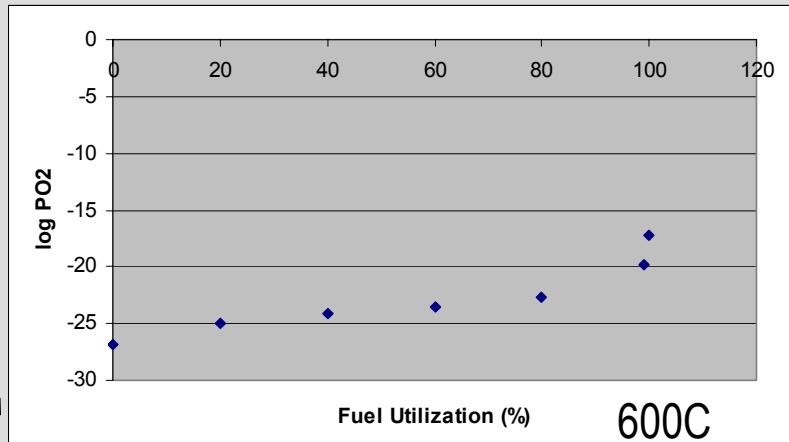
Fuel Utilization	PH <sub>2</sub> O/PH <sub>2</sub>	logPO <sub>2</sub> /600	logPO <sub>2</sub> /800
0	0.031	-26.89	-21.38
20	0.28	-24.98	-19.46
40	0.724	-24.16	-18.64
60	1.56	-23.5	-17.98
80	4.26	-22.62	-17.1
99	102.09	-19.87	-14.34
99.995	1999	-17.27	-11.76

Consider H<sub>2</sub>-3%H<sub>2</sub>O Fuel

# Oxide formation in fuel gases

- Ni & Cu remain metallic up to 99% FU
- Fe, Cr, Al, Si etc. will oxidize at all utilizations
- Most alloys will form Al, Cr, Si base oxides in fuel/ utilized fuel gases

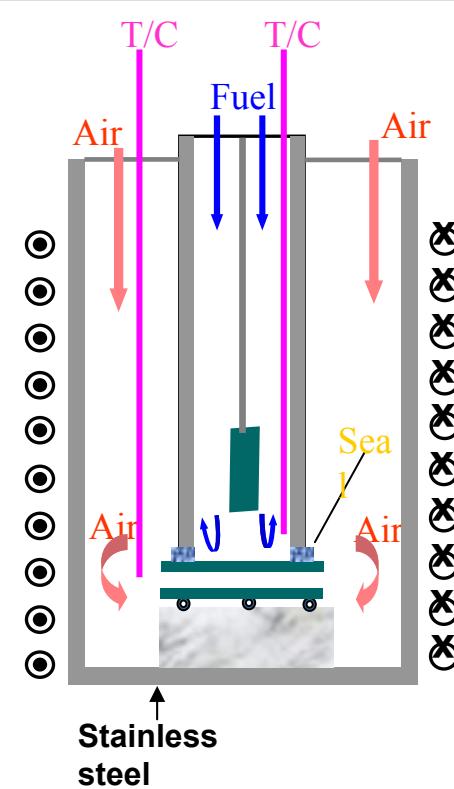
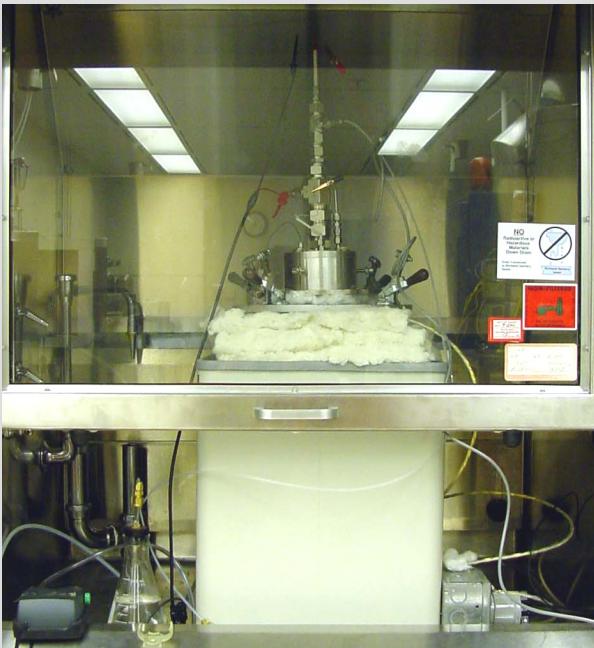
M/MO	PO <sub>2eq</sub> /600	PO <sub>2eq</sub> /800
Ni/NiO	-19.16	-13.91
Cu/Cu <sub>2</sub> O	-12.52	-8.775
Fe/FeO	-24.8	-18.91
Cr/Cr <sub>2</sub> O <sub>3</sub>	-36.21	-27.82
Co/CoO	-20.62	-15.42



# Dual Atmosphere Study

FeSS {  
NiBS {

FSS	Fe	Ni	Cr	C	Mn	Si	Mo	W	Ti	Al	RE
AISI430	Bal.	--	16.0	0.1	1.0	1.0	--	--	--	--	--
Crofer22 APU	Bal.	--	22.0	0.005	0.5	--	--	--	0.08	--	0.06La
E-brite	Bal.	--	26.0	0.001	0.01	0.025	--	--	--	--	--
Haynes 230	1.5	Bal.	22.0	0.10	0.5	0.4	1.4	14	--	0.3	0.02La .005B



## Variables:

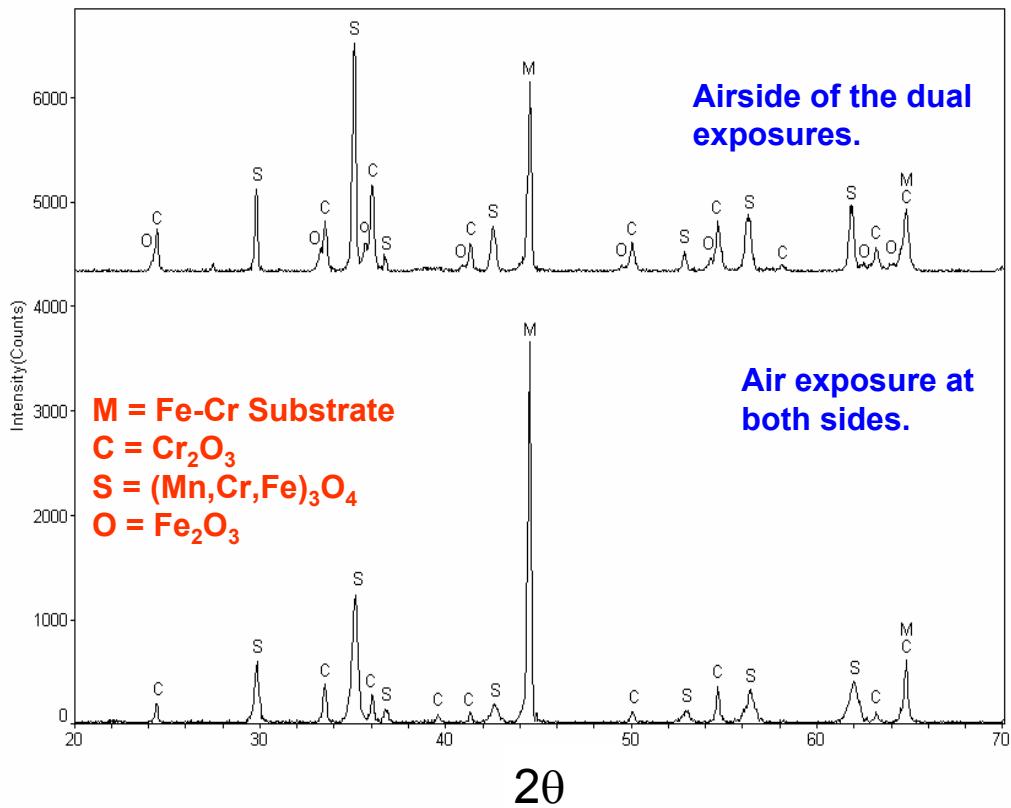
Temperature, 700~800°C  
Time, 300 hours  
Fuel, H<sub>2</sub>+3% H<sub>2</sub>O  
Heating, isothermal and cycling.

## Materials Evaluated:

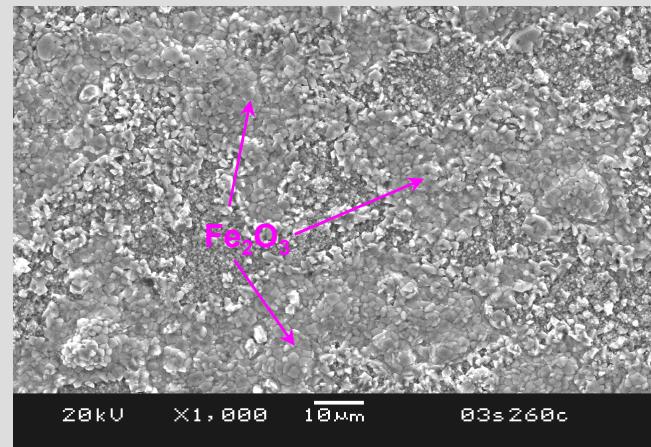
Fe & Ni Base Alloys  
Ag

# Crofer22 APU: Structure of Scales

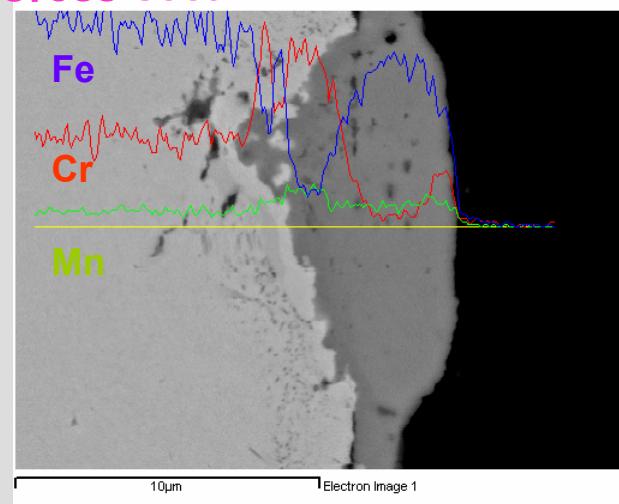
Grown on the coupon in air only and on the air side; heat-treated at 800°C for 300 hours, with three thermal cycles.



Air-side of dual test



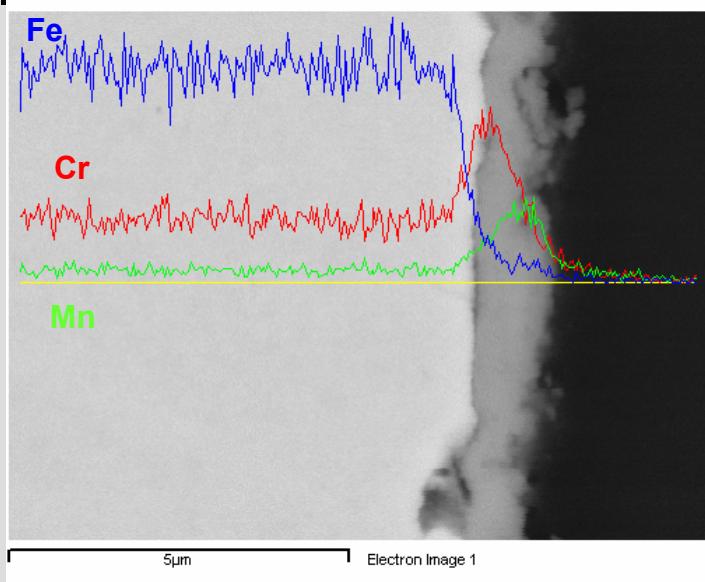
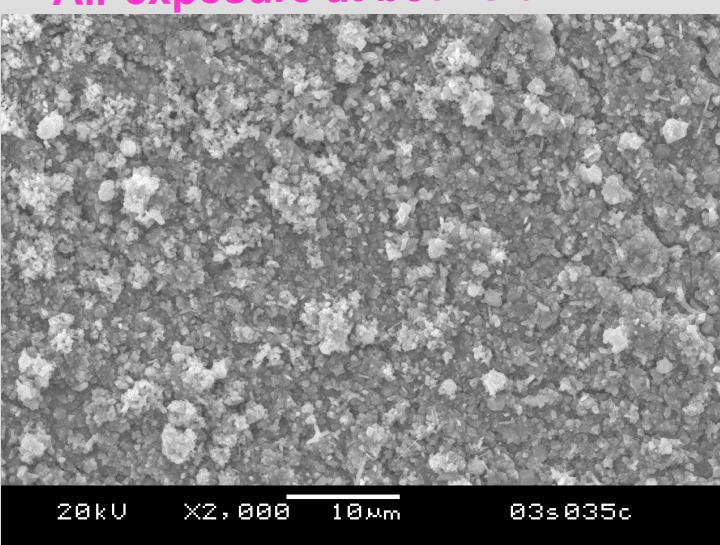
Cross-section: airside of dual test



# AISI430: Scale Microstructures

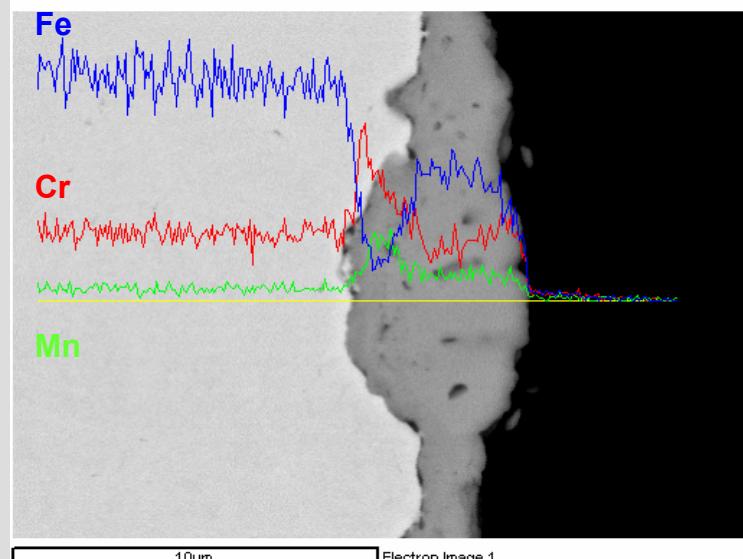
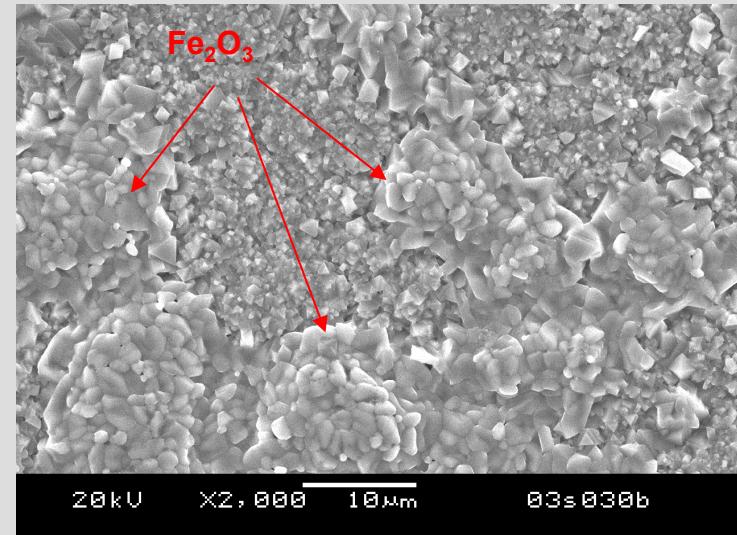


Surface microstructures

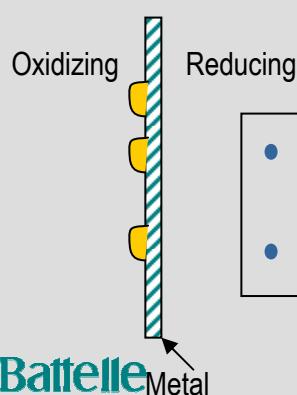
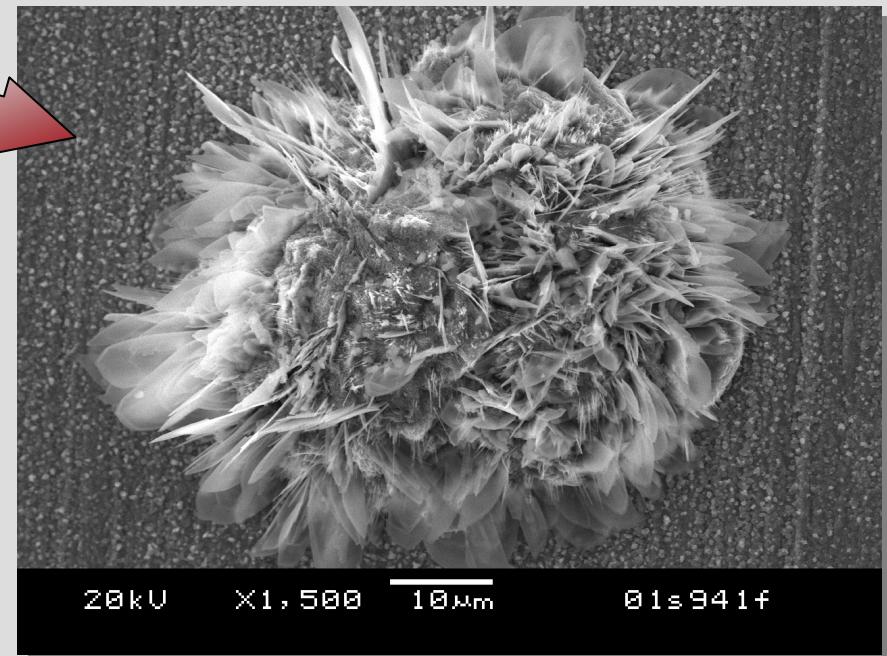
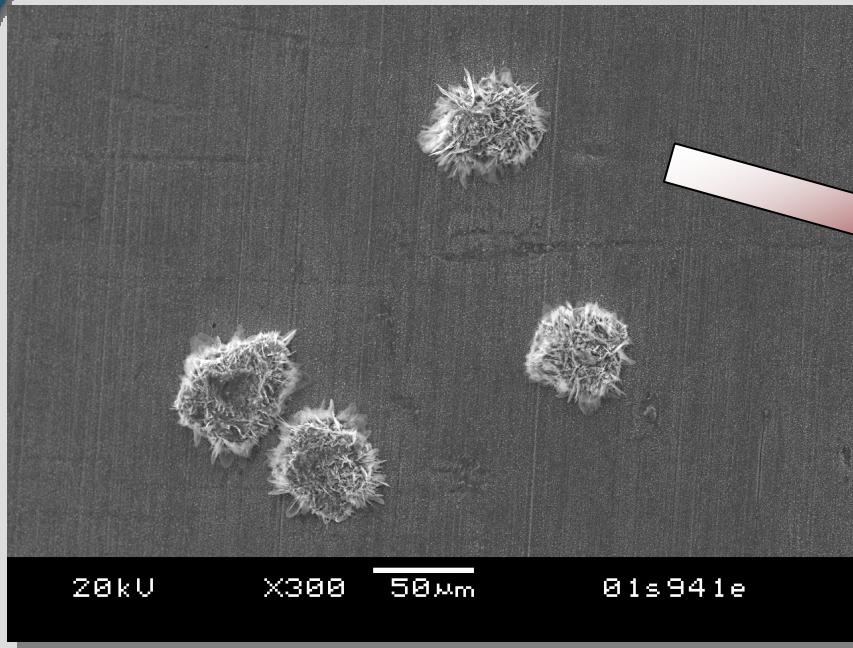


Cross-sections

Air-side of dual exposures



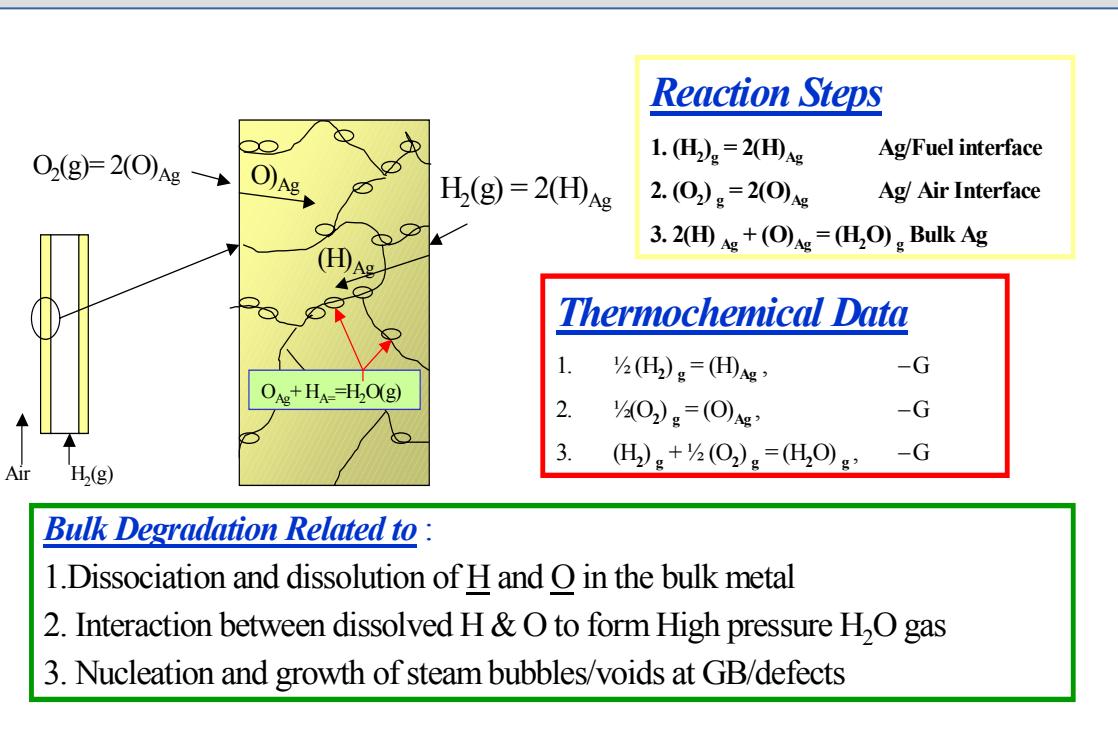
# Localized Overgrowth of Scale



- Localized Scale Overgrowth – FeOx Rich Oxide
- Platelets/ Whiskers Formation- Preferred Growth

# Bi-polar effect

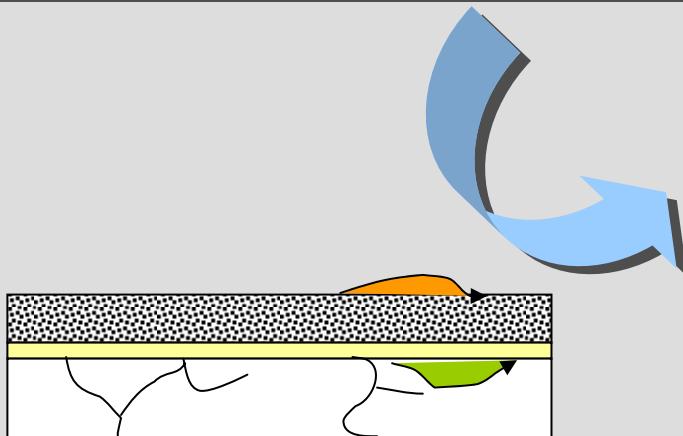
Mechanistic understanding of corrosion processes are being developed for addressing long term performance of materials



# Dual Atmosphere effect

## Presence of multi-oxidant / H<sub>2</sub>O leads to :

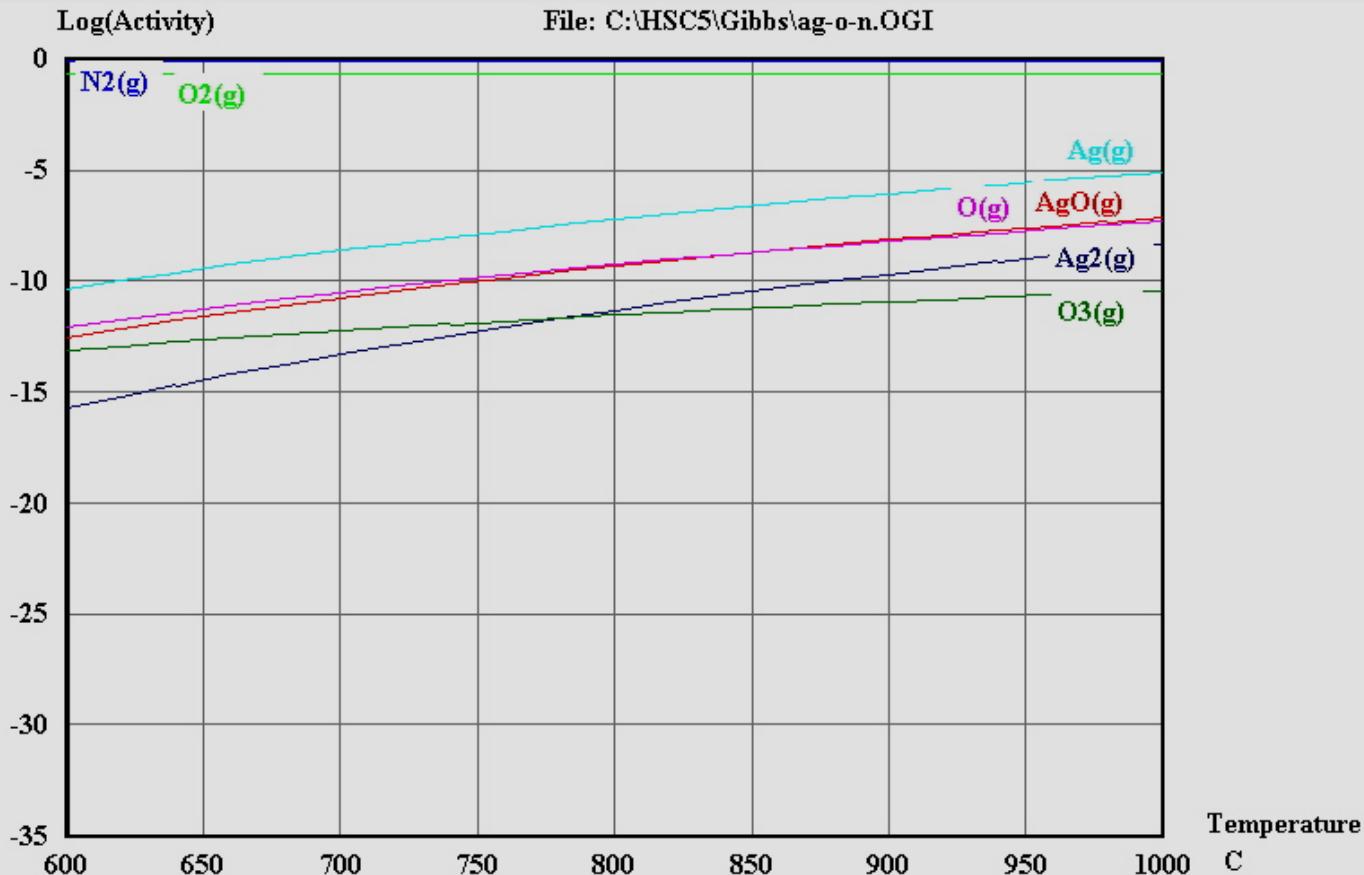
- Accelerated corrosion
- Multi-phase oxide formation
- Uneven metal / metal oxide interface formation
- Localized oxide growth and metal penetration



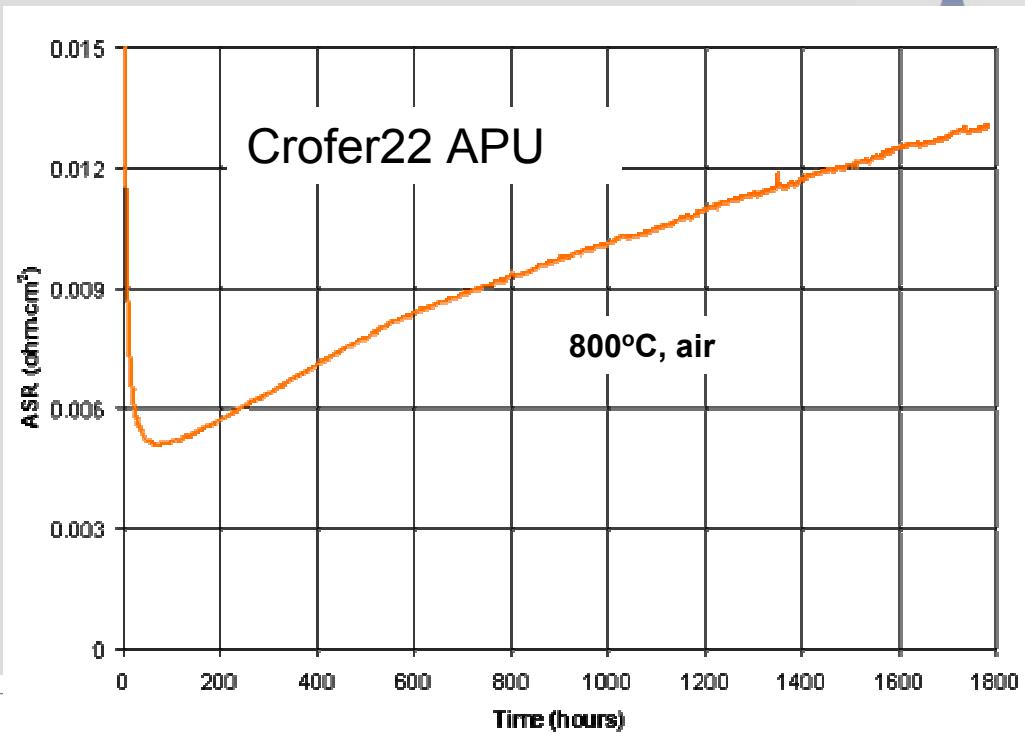
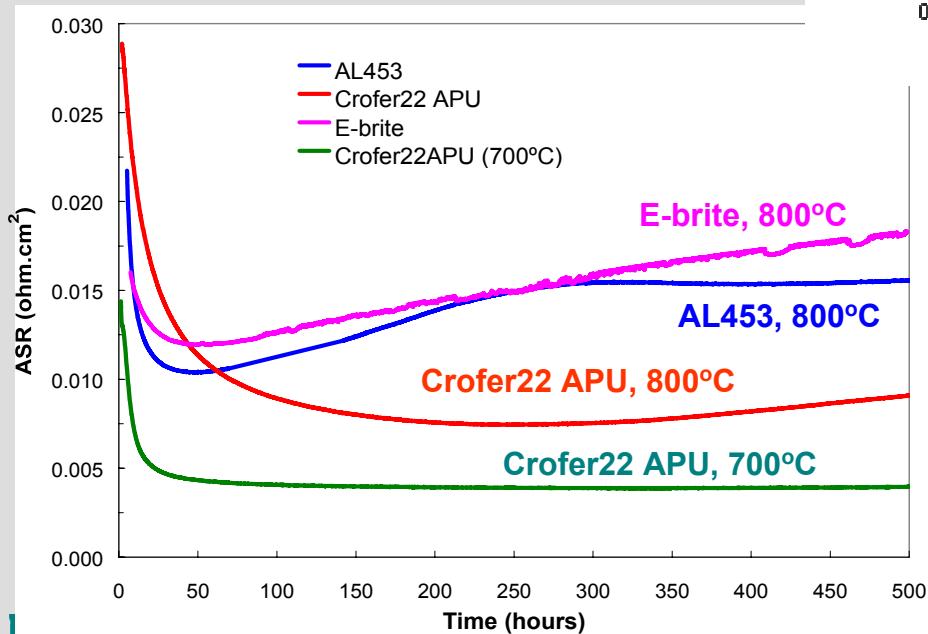
## Possible Reaction Mechanisms:

- Porous oxide formation
- Defect structure modification
- Red / ox gas chemistry

# Silver evaporation in air

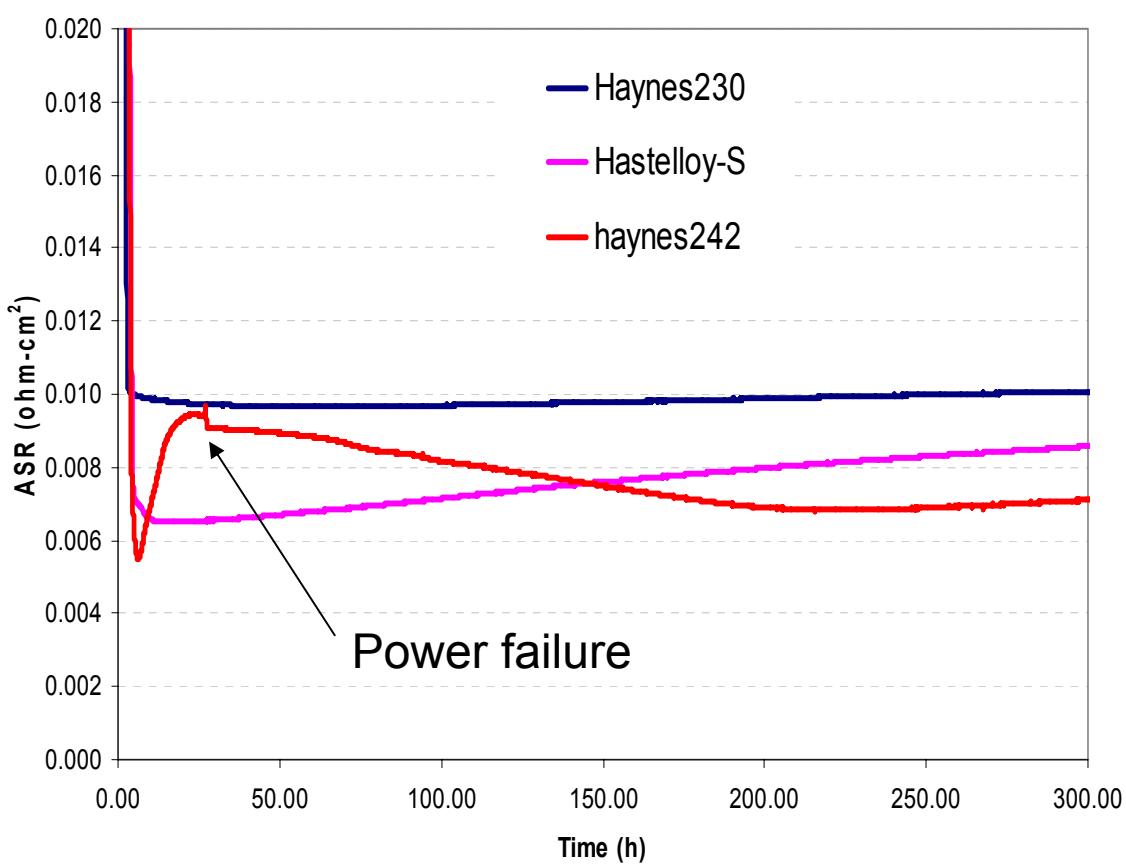


# FSS Scale Electrical Conductivity



**Coupon samples were pre-oxidized in air at temperature for 100h before carrying out tests in air**

# Scale ASR of Ni-based Alloys



**Coupon samples were pre-oxidized in air at temperature for 100h before carrying out tests in air at 800°C**

# Comparison



**Haynes230**

**Ni-base superalloy**

**Ni-22Cr-14W-2Mo-.5Mn**

**Crofer22 APU**

**Stainless steel**

**Fe-22Cr-.5Mn**

<b>Thermal expansion <math>\times 10^{-6} \text{ K}^{-1}</math></b>	15.2 RT-800°C	12.2 RT-800°C
<b>Oxidation resistance <math>\text{Kg, } 10^{-13} \cdot \text{g}^2 \cdot \text{cm}^{-4} \cdot \text{s}^{-1}</math></b>	0.36, 800°C 0.05, 700°C	7.0, 800°C 2.0, 700°C
<b>ASR, <math>\text{m}\Omega \cdot \text{cm}^2</math> After 600h of oxidation</b>	10.0, 800°C 5.0, 700°C	9.0, 800°C 4.0, 700°C
<b>Dual atmosphere Corrosion resistance</b>	Enhanced formation of uniform chromia scale	Grow hematite to accelerate attack
<b>Ultimate tensile strength, <math>\sigma_u</math> (MPa)</b>	865, RT 605, 760°C	443, RT <100, 760°C
<b>Manufacturability</b>	<b>Very easy</b>	<b>Fairly easy</b>
<b>Raw materials cost</b>	<b>Fairly expensive</b>	<b>Inexpensive</b>

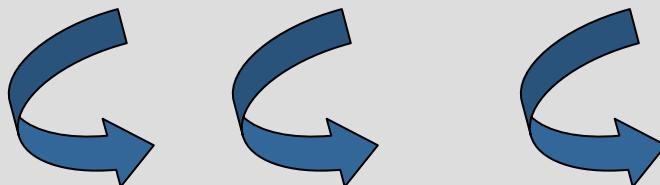


# Interaction with Seal

# Interaction with Glass seals

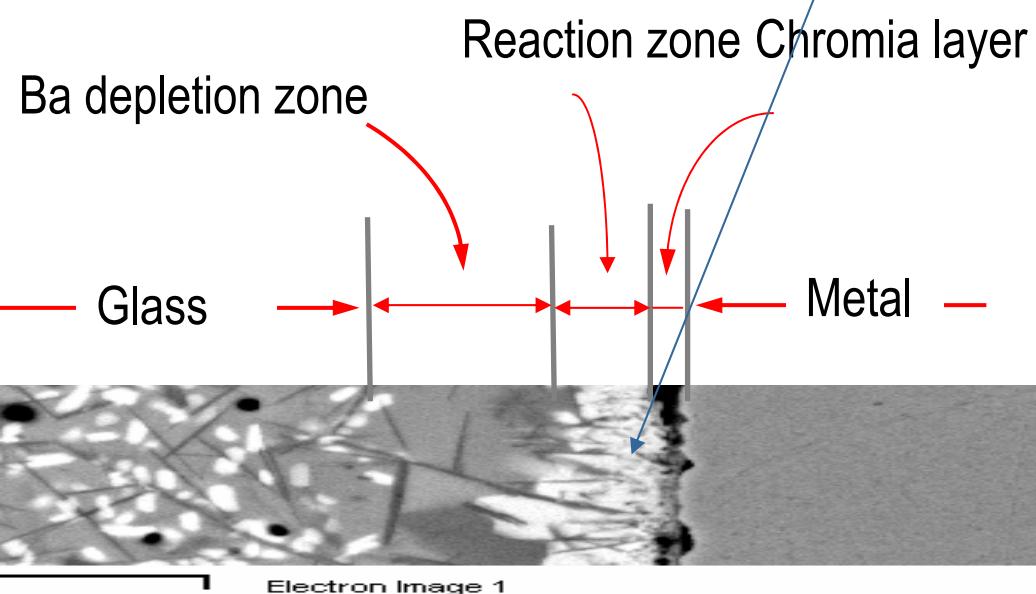
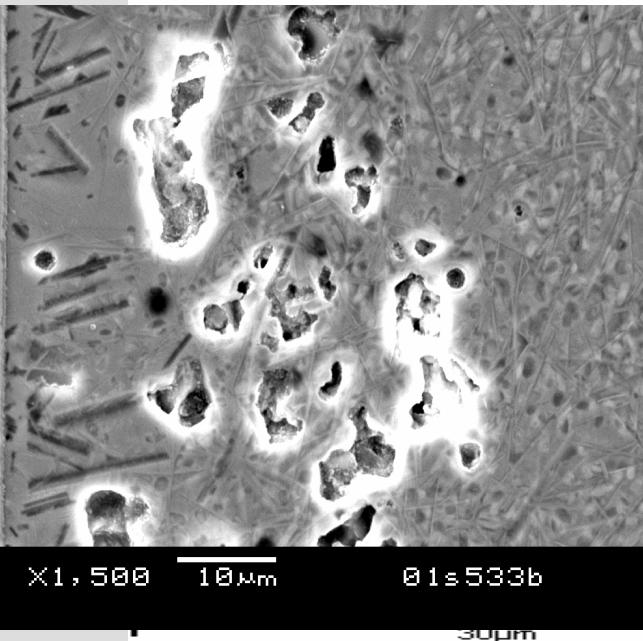
For un-optimized alloys:

- Weaker interface
- Cr dissolution
- Localized porosity formation at the interface



Modified interface/Coating improves the strength and stability

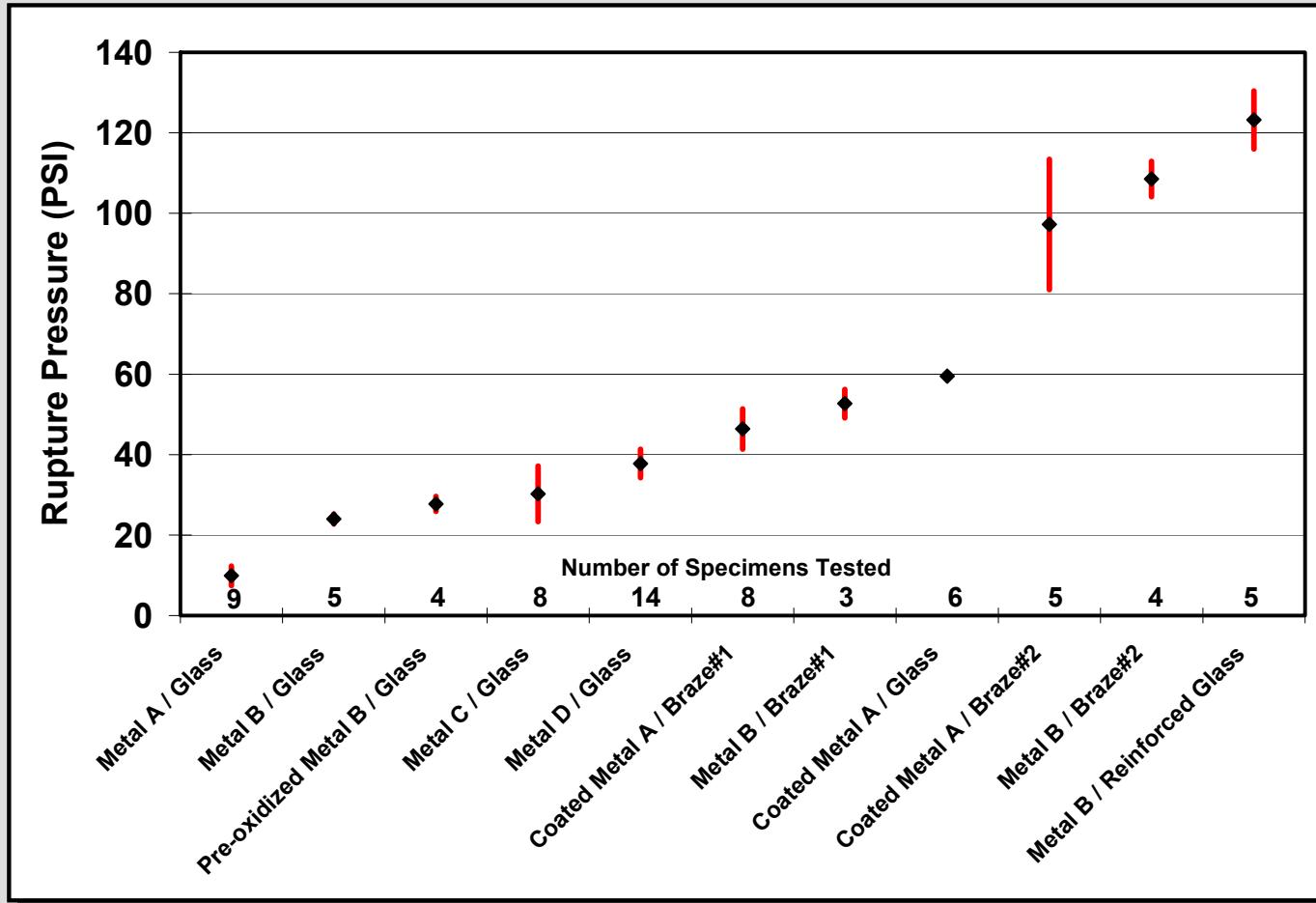
# Un-optimized Seal/Alloy Interfaces



**Localized porosity formation  
at the interface**

**Weakening of interfaces  
due to secondary phase  
formation**

# Improvement of Seal Strength for Generation 3

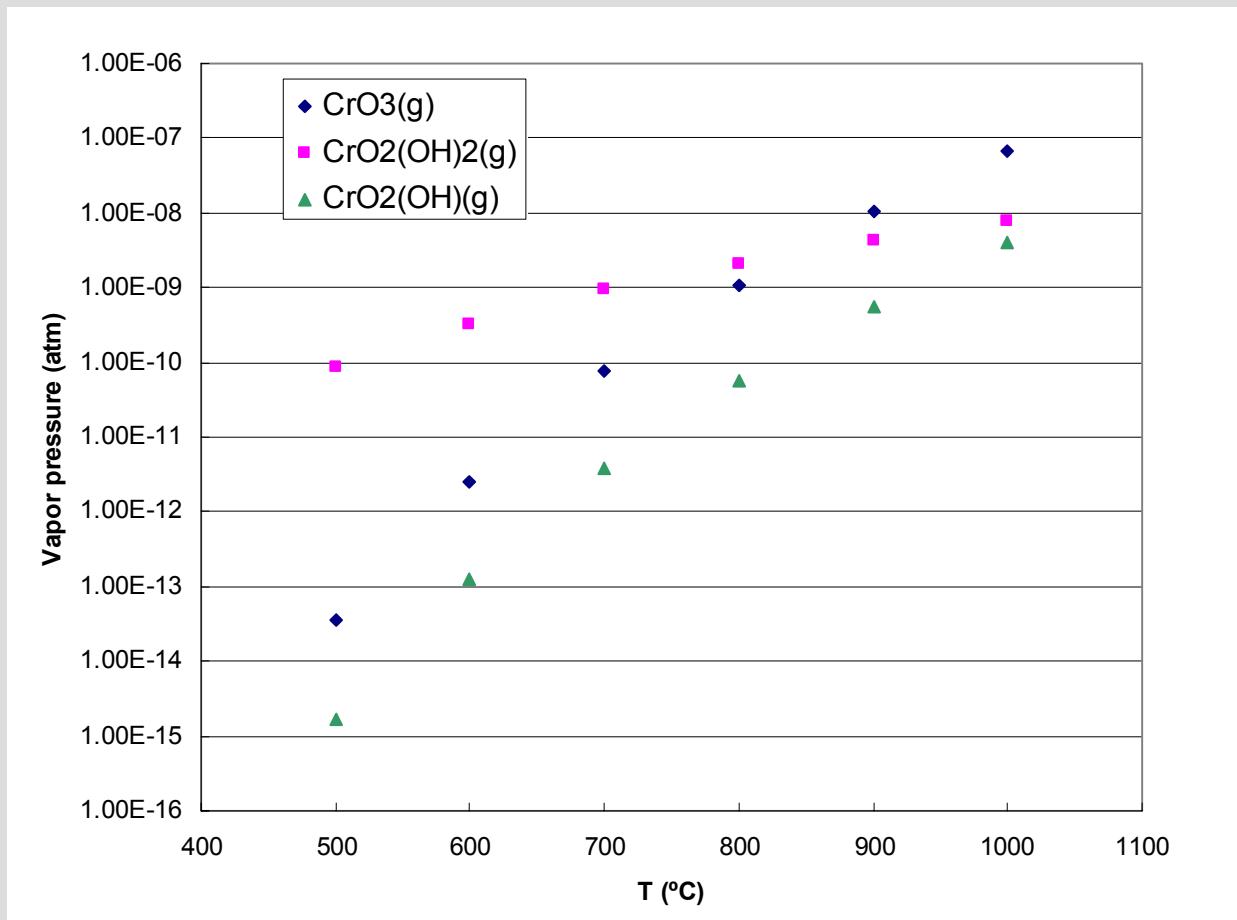


(Slide Courtesy of Delphi/BMI)



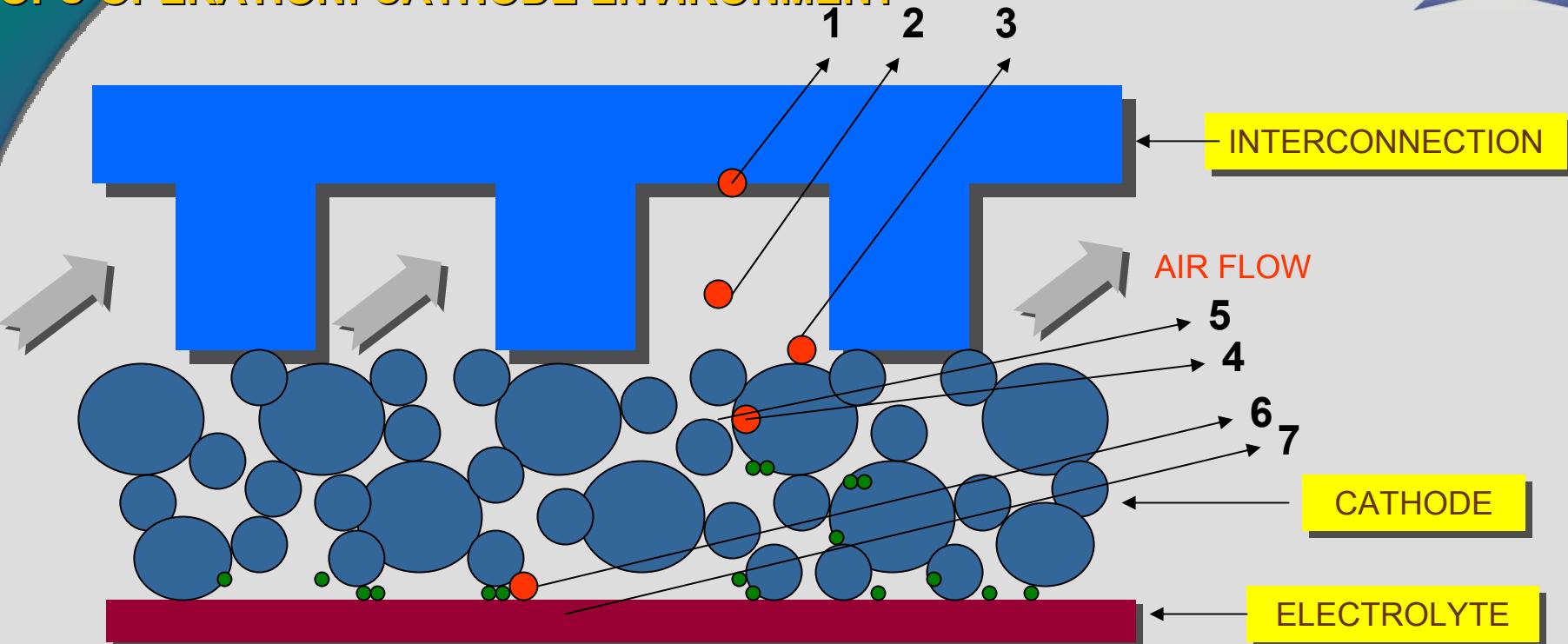
# Cr Evaporation and Electrode Poisoning

# Chromium Species Evaporation



Calculated equilibrium vapor pressure of Cr species ( $\text{CrO}_3$ ,  $\text{CrO}_2(\text{OH})$ , and  $\text{CrO}_2(\text{OH})_2$ ) above  $\text{Cr}_2\text{O}_3$  in air (w/ 3% water) at 1 atm.

# FORMATION, TRANSPORT AND INTERACTION OF CR SPECIES DURING SOFC OPERATION: CATHODE ENVIRONMENT



- 1: CHROMIUM EVAPORATION FROM IC SURFACE
- 2: GAS PHASE TRANSPORT OF CHROMIA VAPOR
- 3: CONTACT WITH CATHODE SURFACE
- 4: REACTION WITH CATHODE SURFACE
- 5: DIFFUSION INTO CATHODE
- 6: REDUCTION AND DEPOSITION AT CATHODE/ELECTROLYTE INTERFACE
- 7: DIFFUSION INTO ELECTROLYTE/ BARRIER LAYER

# FORMATION, TRANSPORT AND INTERACTION OF CR

## CHROMIA EVAPORATION FROM IC SURFACE



## GAS PHASE TRANSPORT OF CHROMIA VAPOR



## SURFACE COVERAGE OF AIR ELECTRODE



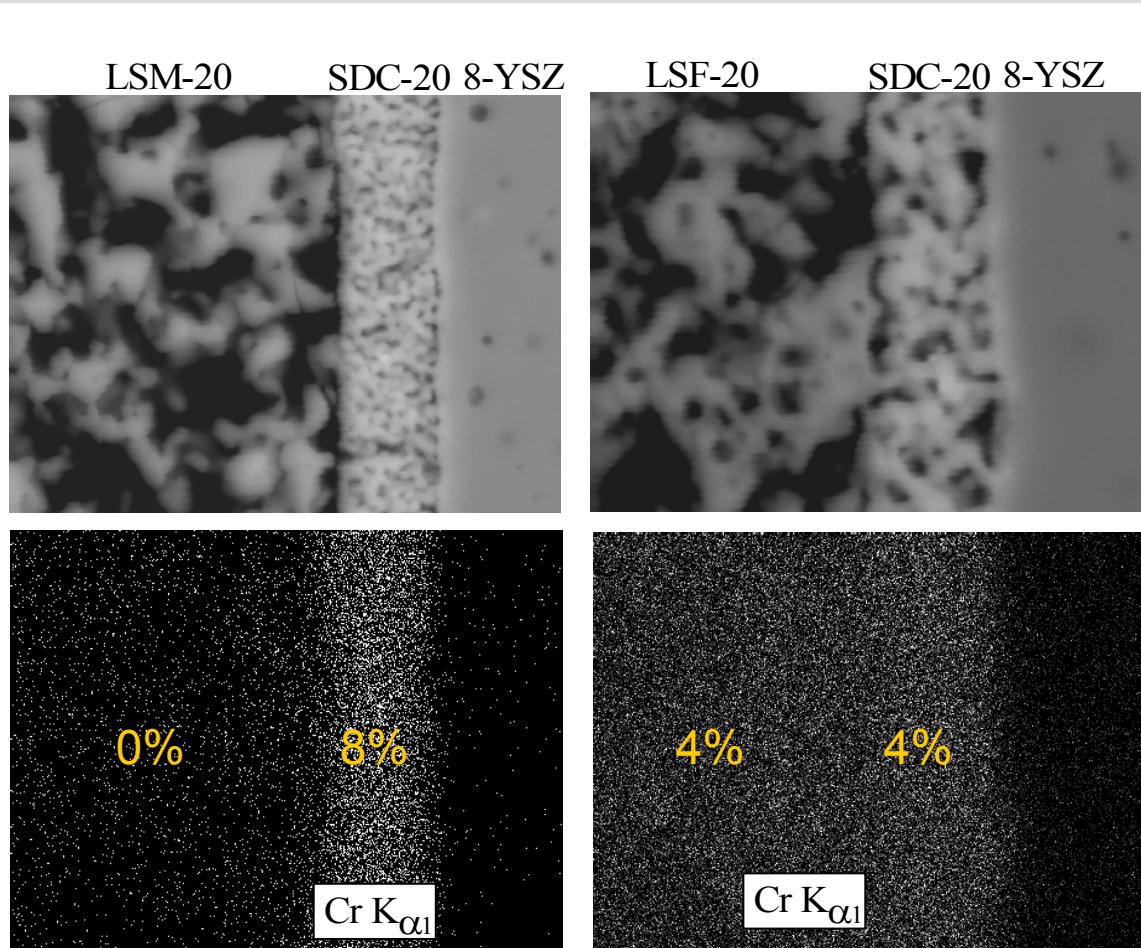
## INTERACTION WITH AIR ELECTRODE



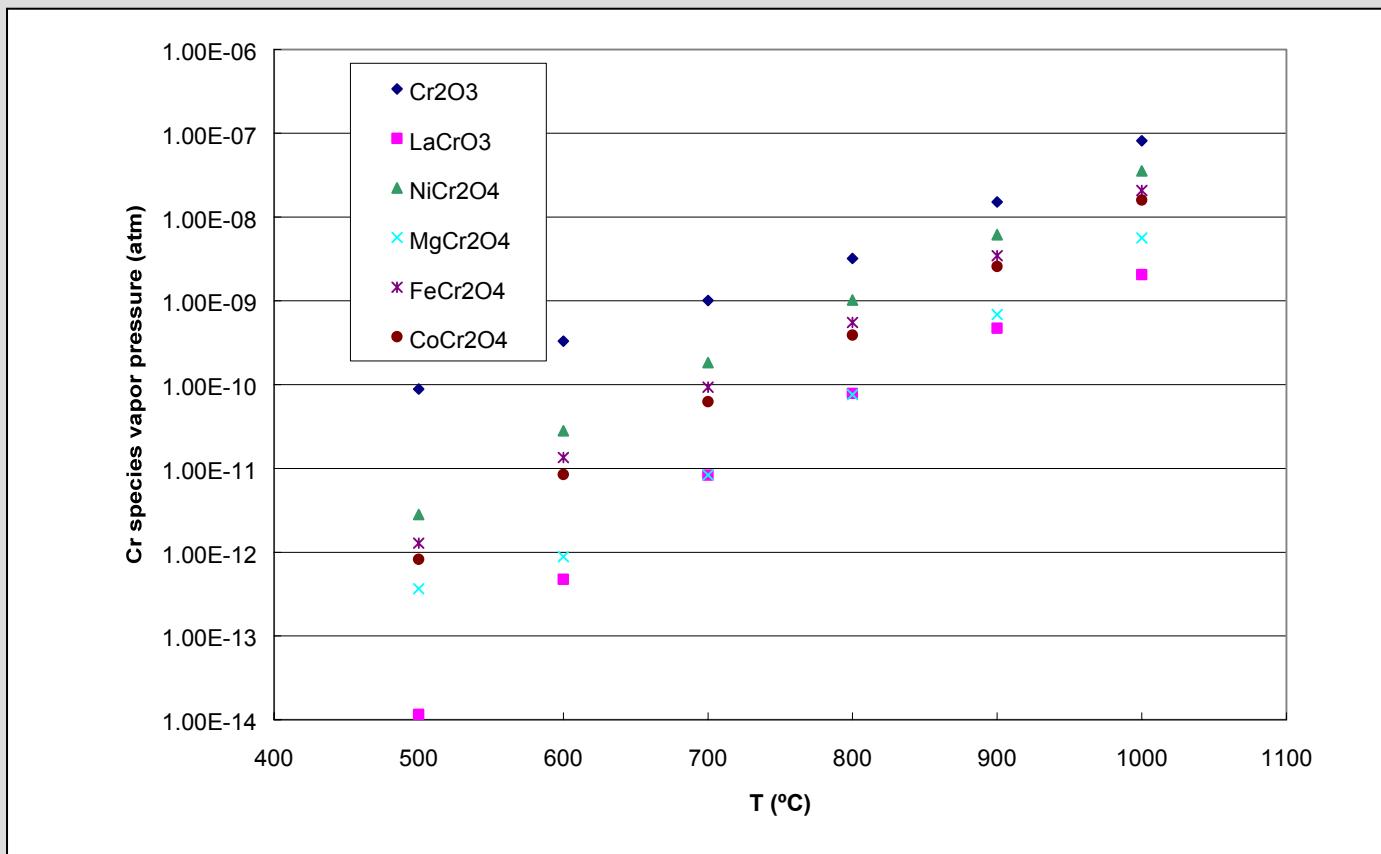
## REDUCTION AND DEPOSITION



# Cr Deposition in Cathode



# Chromium Species Evaporation



Calculated total equilibrium vapor pressure of Cr species (CrO<sub>3</sub>, CrO<sub>2</sub>(OH), and CrO<sub>2</sub>(OH)<sub>2</sub>) above the indicated oxides in air (w/ 3% water) at 1 atm.

# Cr Evaporation and its effects

Cr poisons cathode

Severity of poisoning varies with materials and cell/stack design



## Mitigation approaches:

- Reduce Cr activity in the oxide ( lower partial pressure of Cr above oxide)
- Add “Cr absorbing “ materials at the interface
- Provide Cr free coatings for IC
- Optimize gas flow path to allow “Flow By” situation



# Coatings and Claddings

# Cladded Interconnect Structures



## Concept



After rolling



After heat treating

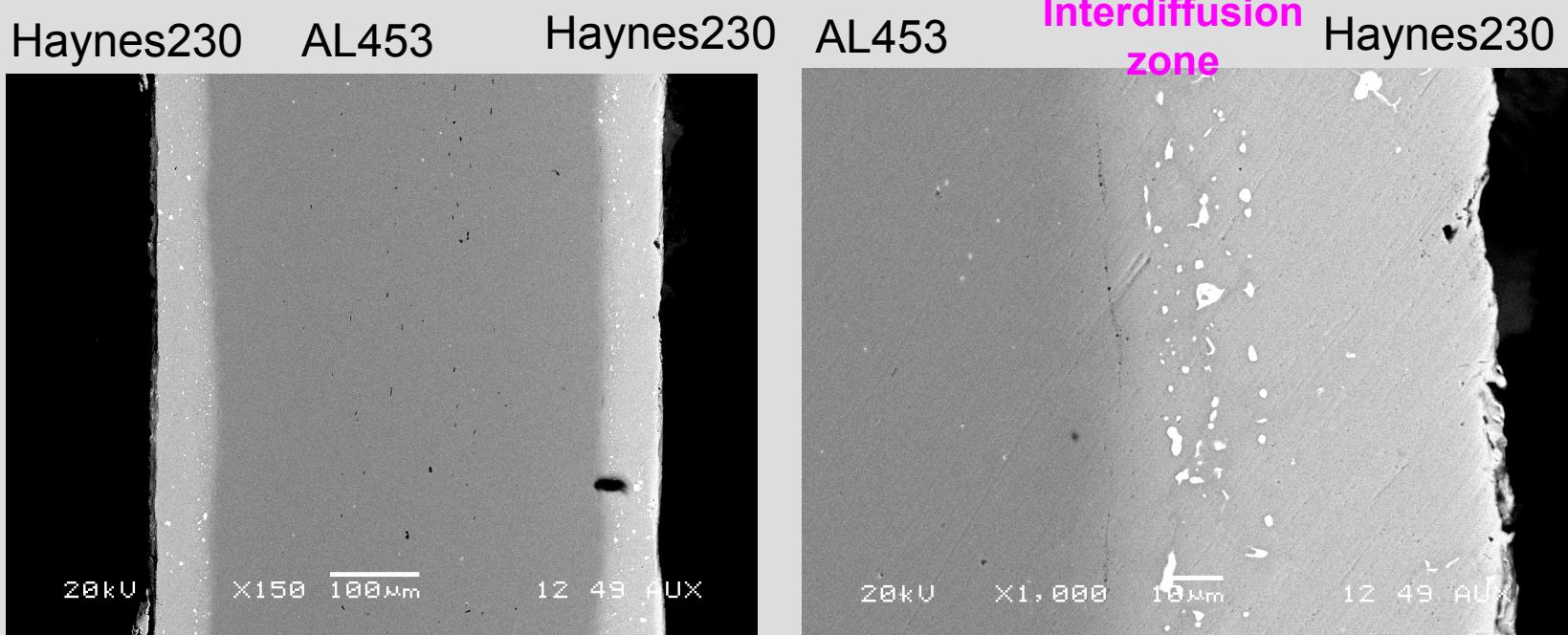
## Advantages

- Integrate advantages of different alloys, while avoiding disadvantages.
  - ❖ Solve the issue of thermal expansion mismatch;
  - ❖ Optimize the interconnect mechanical and structural stability.
- Allow to address cathode- and anode-side issues separately;
- Mass production and very cost effective.

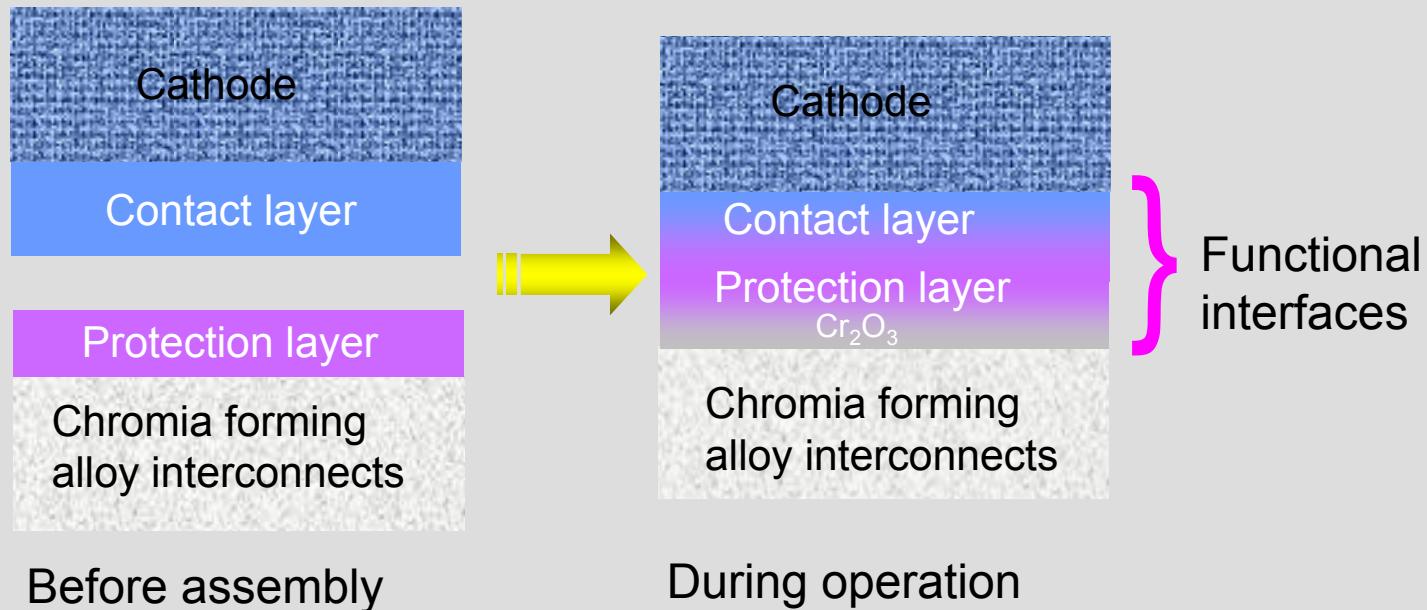
# Proof of Concept



Sample No	Cladding couples	Final rolling gauges
System1	Inconel625    AL453CRE    Inconel625	0.010"
System2	Inconel625    AL453CRE    AISI316	0.010"
System3	Haynes230    AL453CRE    Haynes 230	0.010"
System5	Haynes230    AL453CRE    Haynes 230	0.020"
System6	Haynes230    AL453CRE	0.010
System7	Haynes230    AISI430	0.020"
system8	Haynes230    AISI430	0.010"



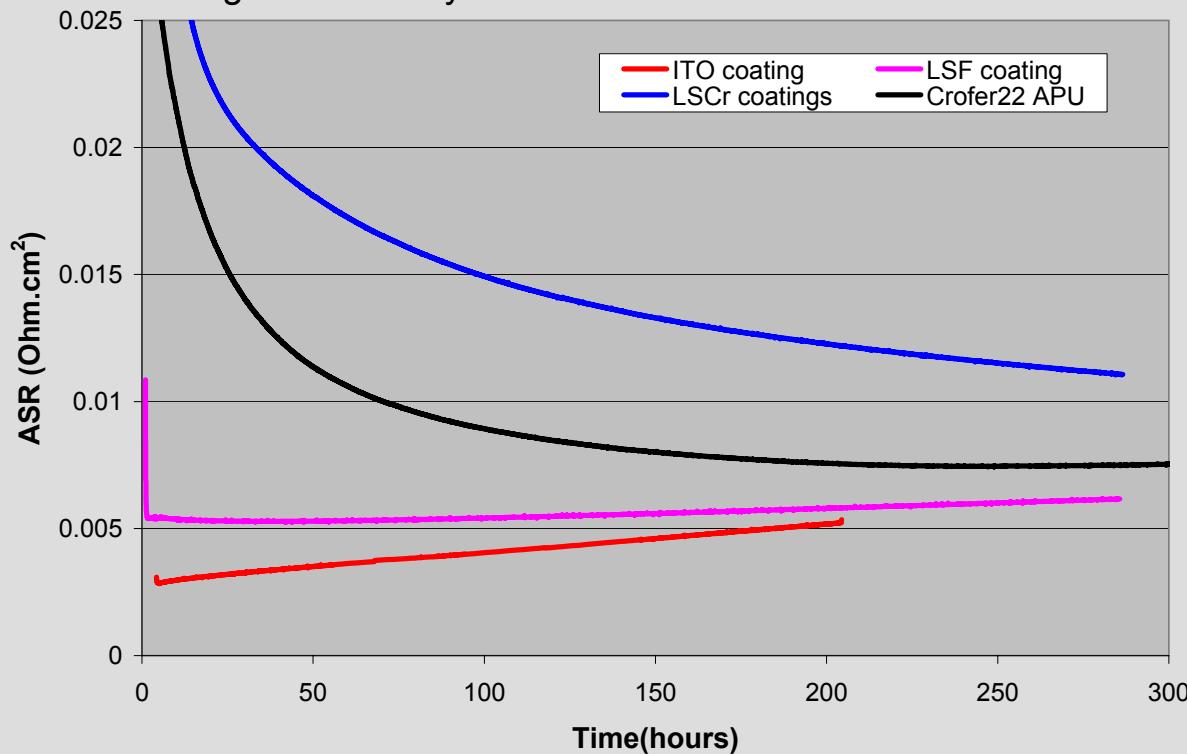
# Cathode-Side Functional Interfaces



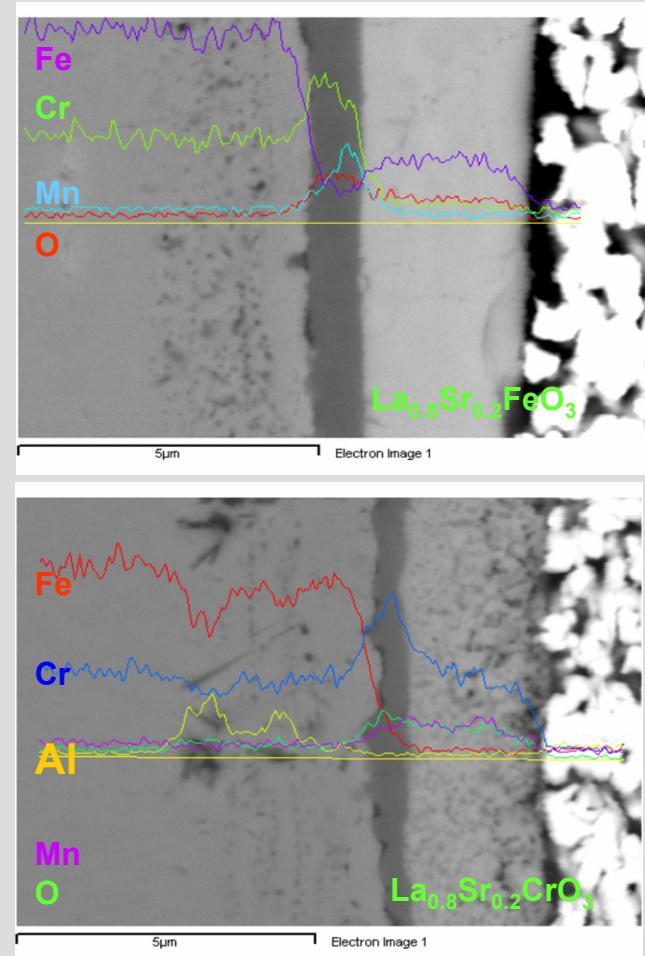
- Protection layer acts as a mass barrier to mitigate or prevent Cr migration via both gas transport and solid state reactions, as well as to decrease electrical contact resistance. The subsequently grown chromia sub-scale serves as cation and anion transport barrier, protecting the alloy interconnect.
- Contact layer promotes contact between cathodes and interconnects, and helps minimize interfacial resistance and power loss.

# Perovksite Protection Layers

- The provskite coatings decrease electrical resistance and mitigate or prevent Cr migration;
- The growth rate of the chromia beneath the coatings and the eventual scale depends on the ionic conductivity of coatings.
- Long term stability needs to be further studied.



Both bare and coated samples were pre-oxidized in air at 800°C for 100h before carrying out tests in air at 800°C.

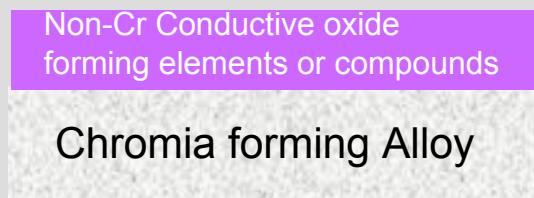


# Development of Protection Layers

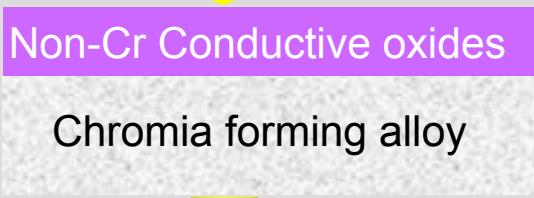


## Concept

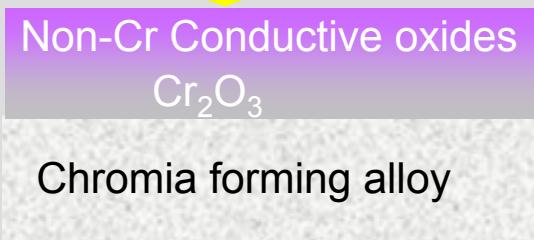
Starting Materials



After thermal treatment



During SOFC operation

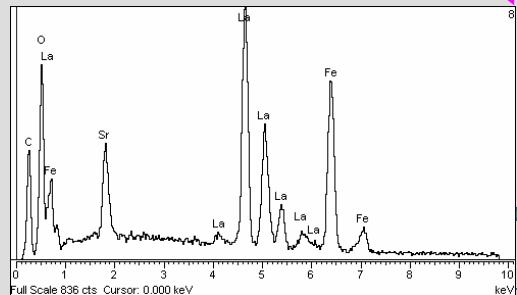
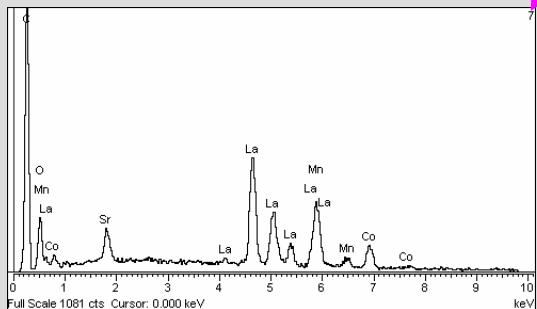
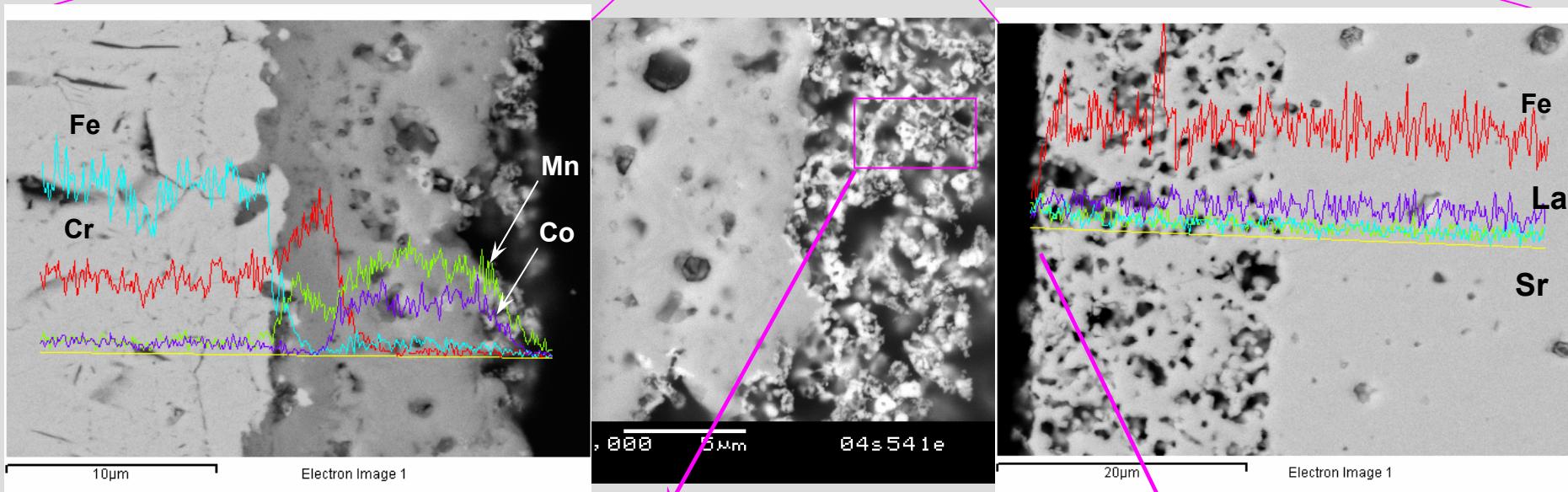
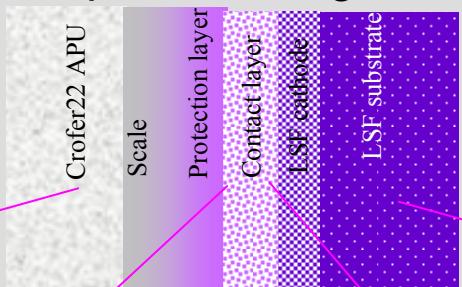


- The conductive oxide top layer acts as a mass barrier to prevent Cr migration via both the gas transport and solid state reaction, as well as to decrease electrical contact resistance.

- The subsequently grown chromia sub-scale serves as cation and anion transport barrier, protecting the alloy interconnect.

# SEM/EDX of Cross-Section

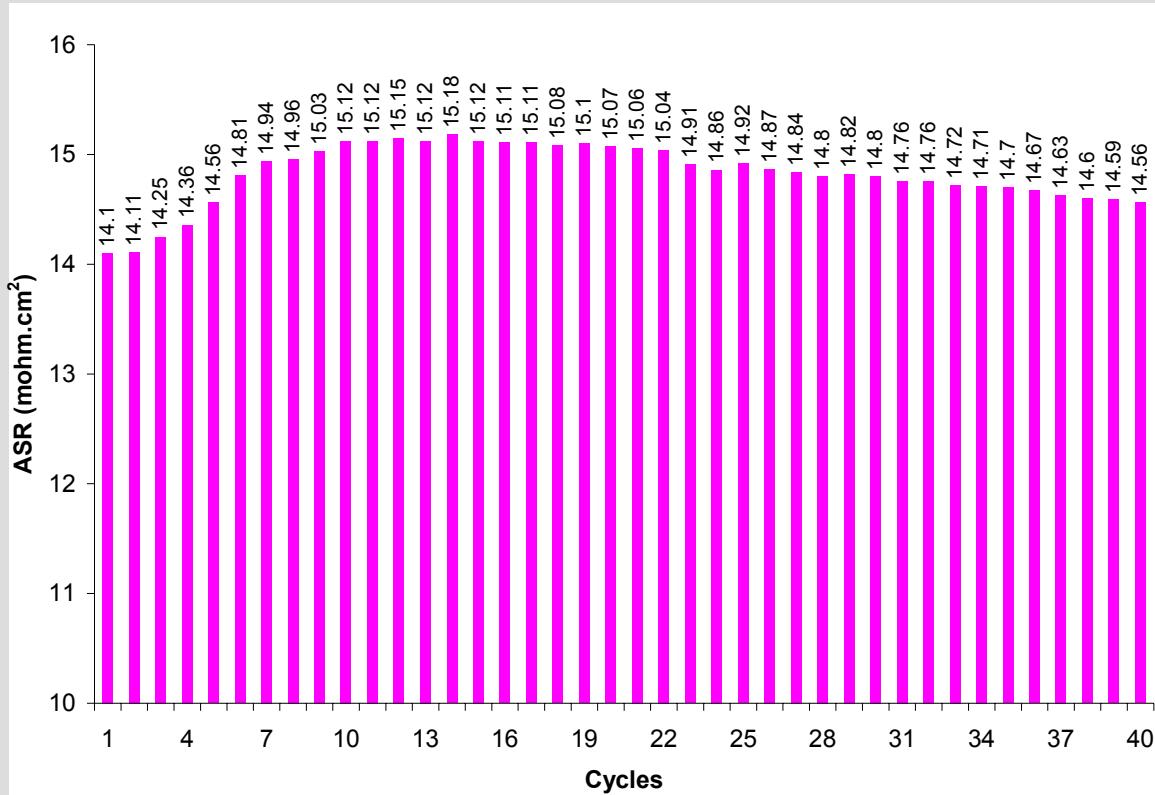
No Cr activity at the surface of spinel coating after 1,000h at 800°C in air



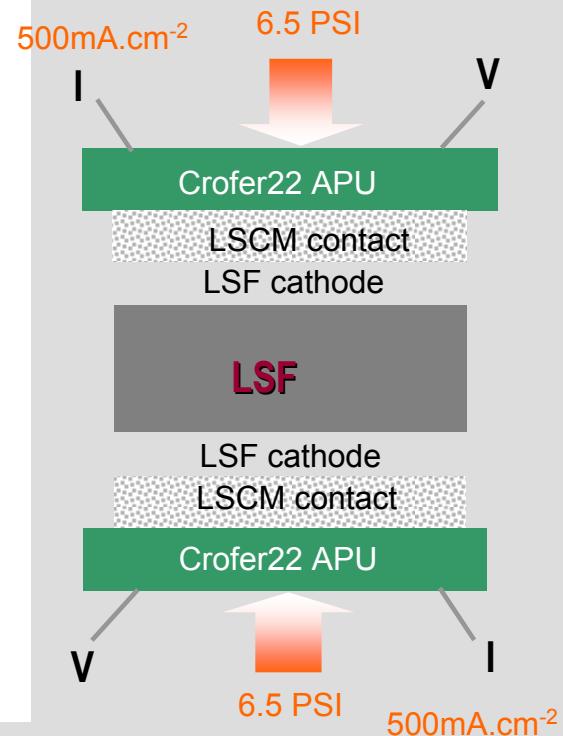
# Interfacial ASR of Crofer22 APU Grown with Spinel Protection Layers



The  $(\text{Mn},\text{Co})_3\text{O}_4$  spinel protection layer on Crofer22 APU minimizes the interfacial resistance;  $(\text{La}_{0.8}\text{Sr}_{0.2})\text{Co}_{0.5}\text{Mn}_{0.5}\text{O}_3$  used electrical contact.

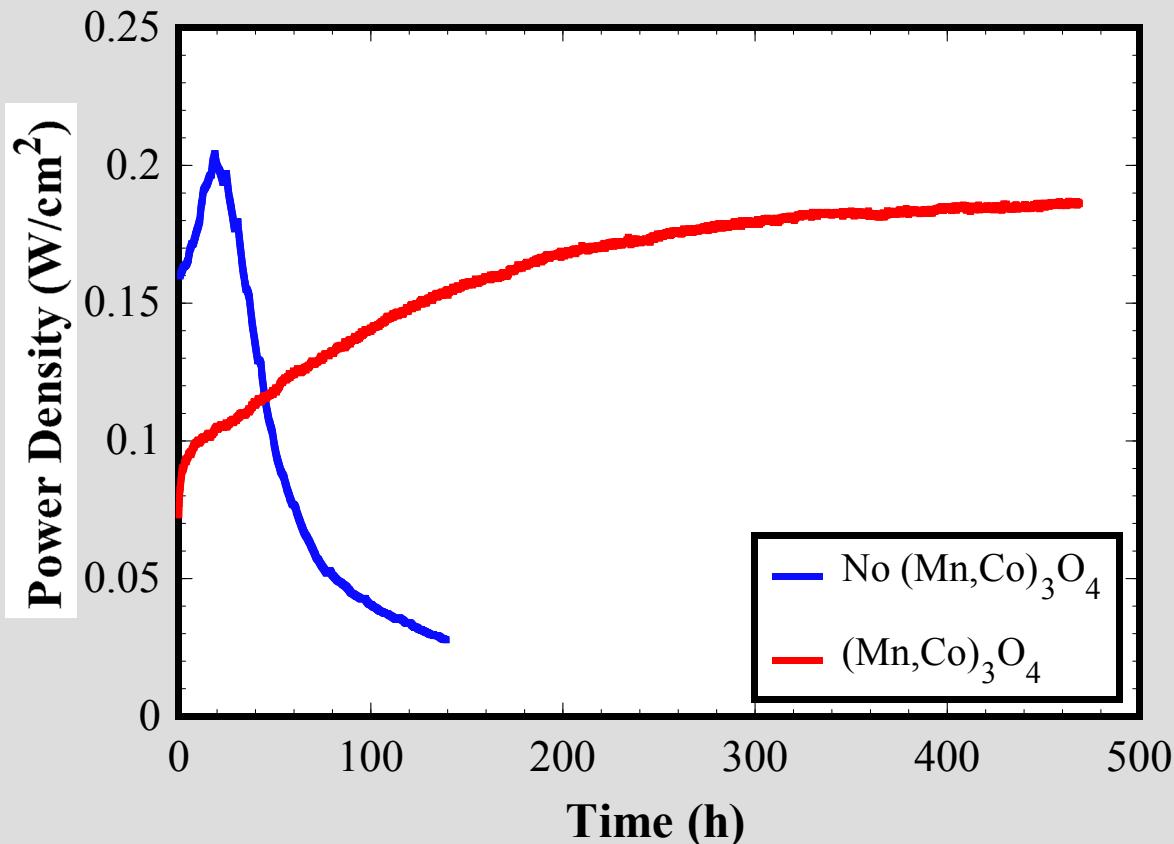


Thermal cycles: 80-800°C



$$ASR_{cathode/int erconnect} = \Phi(scale, contacts, reactions)$$

# Cr mitigation w/ Mn Co spinel surface layer



Anode supported cell w/ LSM-20 with and without  $(\text{Mn},\text{Co})_3\text{O}_4$  protective layer on Crofer foil.

# Summary

- Alloys show promise for IC applications due to low cost, ease of fabrication, high thermal conductivity and low electrical resistance.
- Issues to be addressed include oxidation and corrosion under SOFC operating conditions
  - Metal loss (localized, carburization, sensitization, scale spalling etc.)
  - Increasing electrical resistance
  - Cr evaporation / Poisoning
  - Interaction with seals and contact materials
- Development approaches include alloy modifications, coatings, claddings.
- Essential to focus on system solution (complete electrode – contact materials – interconnect structure and materials)

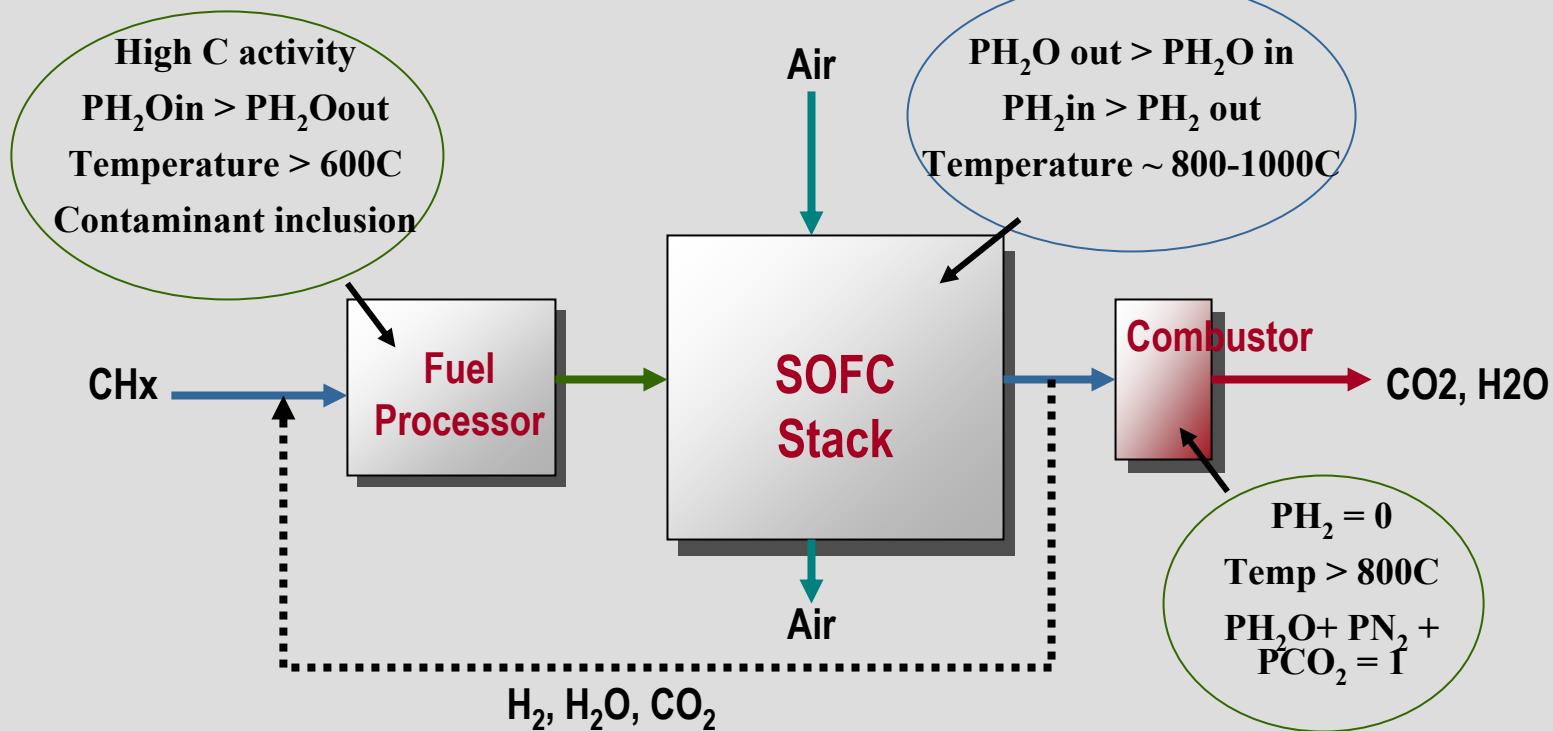
# Acknowledgements

- US DOE Office of Fossil Energy
  - SECA Core Technology Program
    - Wayne Surdoval, Lane Wilson, Don Collins and Travis Schultz
  - PNNL Technical Staff
  - Professor G.H. Meier for helpful technical discussions
  - Dr. N.Q. Minh of GE Power Systems for discussions and suggestions

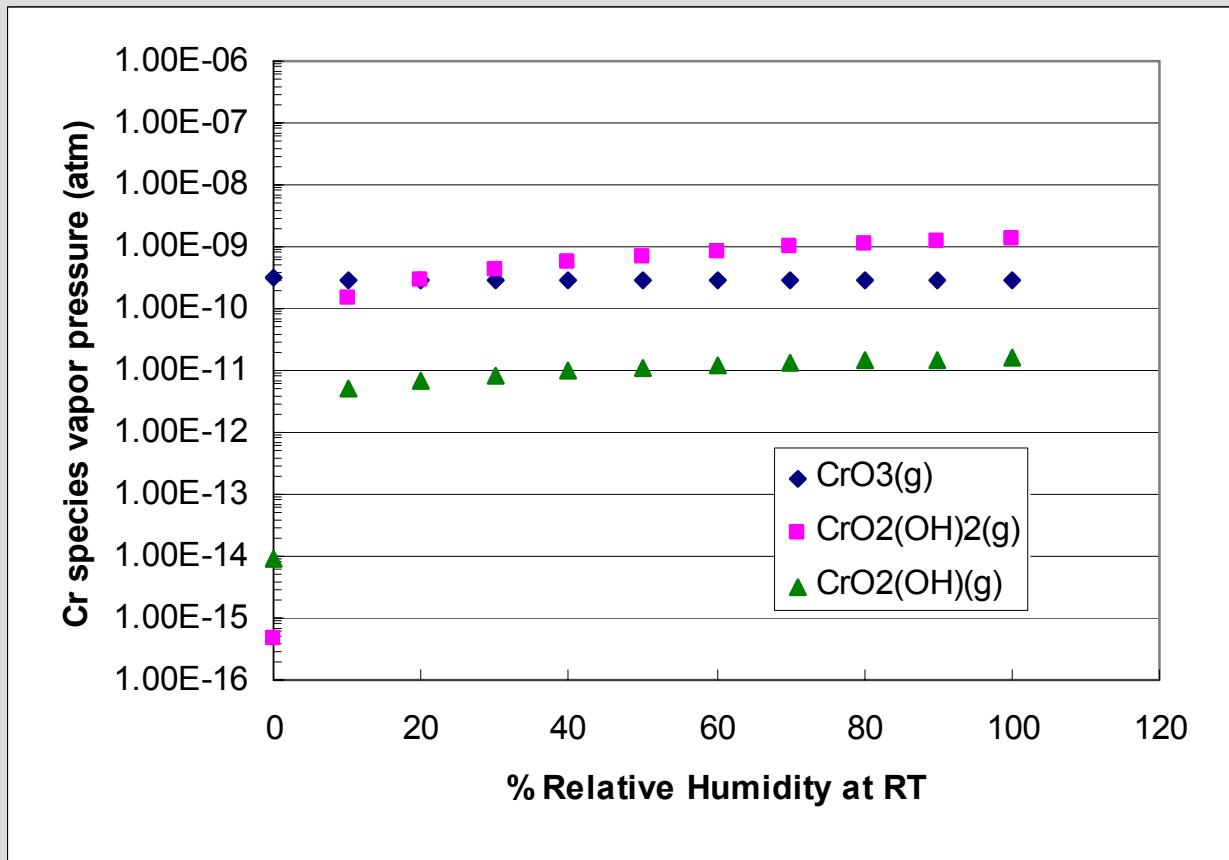
# Workshop Objectives and Goals

- Utilize technical expertise of attendees to address interconnect challenges
- Achieve consensus regarding the technical status, issues and on going activities
- Identify and prioritize potential approaches for solving remaining challenges
- Develop a technology “Road Map” for future R&D activities

# SOFC System



# Chromium Species Evaporation



Calculated equilibrium vapor pressure of Cr species ( $\text{CrO}_3$ ,  $\text{CrO}_2(\text{OH})_2$ , and  $\text{CrO}_2(\text{OH})$ ) as a function of relative humidity in air above  $\text{Cr}_2\text{O}_3$ . Temperature: 750°C; Pressure: 1 atm.